



Verification of High-Speed Links through IBIS-AMI Models

Ganesh Rathinavel, Sr. Application Engineer – AMS/SI

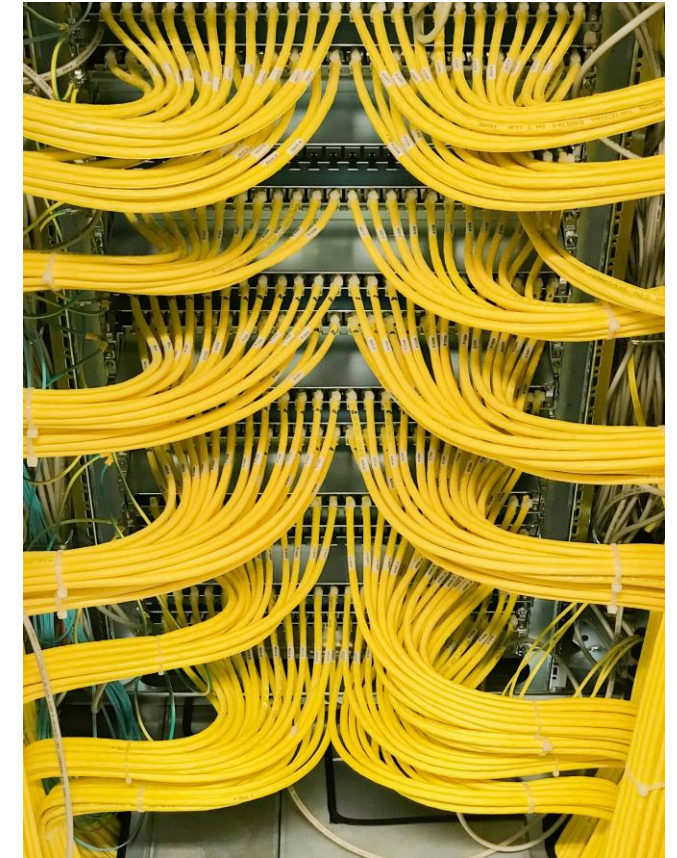
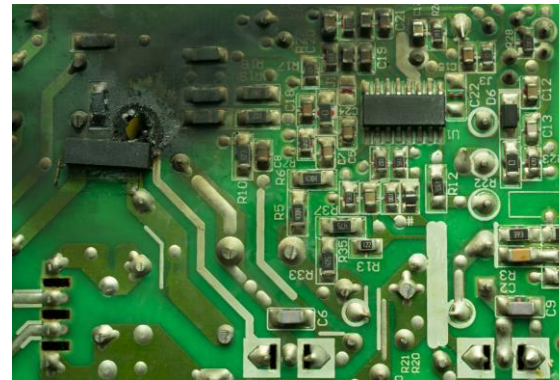


Outline

- Introduction to high-speed links
- System-Level modeling workflow
- Performance verification
 - Statistical Domain
 - Time-Domain
- Generation of IBIS-AMI
- Regression checks
- Channel Pre-layout and Post-layout
- Compliance Checking
- Summary

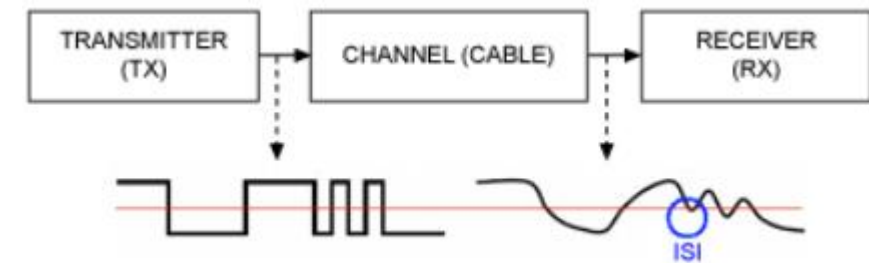
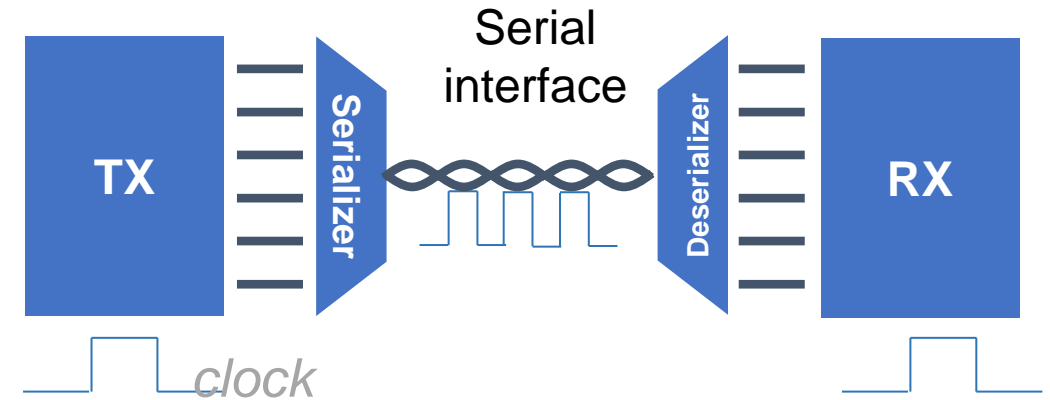
Introduction to High-Speed Links

- High speed digital links or wired links are ubiquitous
- Wide variation of speed and applications, operating conditions
- Limited ports requiring multiplexing at high-speeds
- Growing demand of higher data rate and throughput

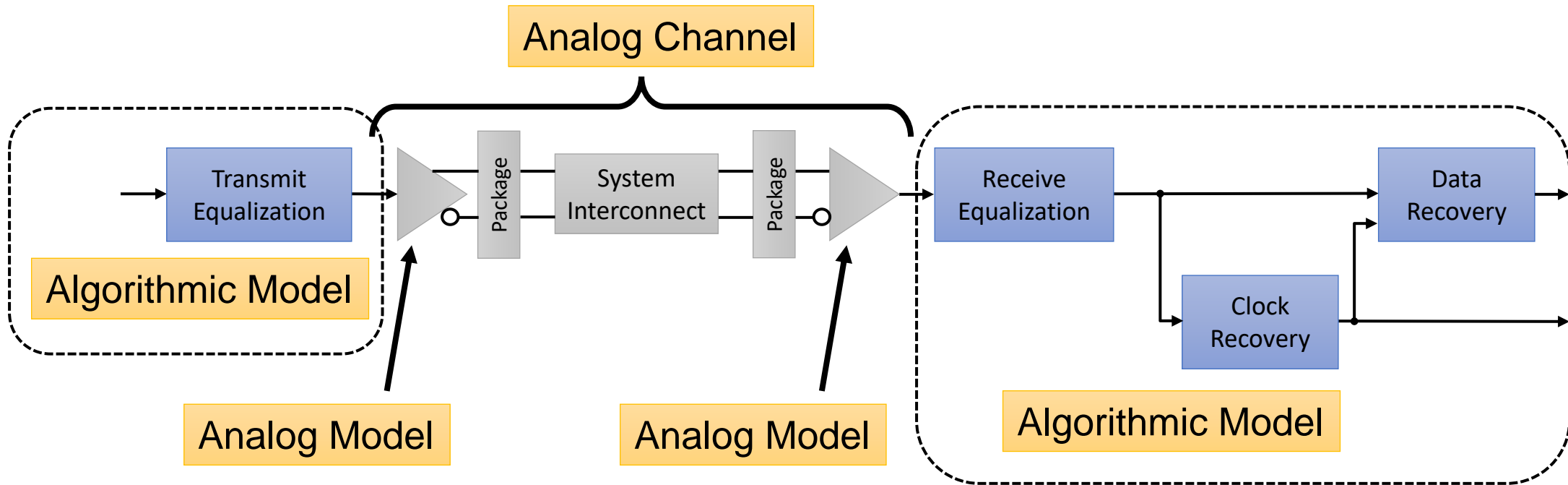


SerDes

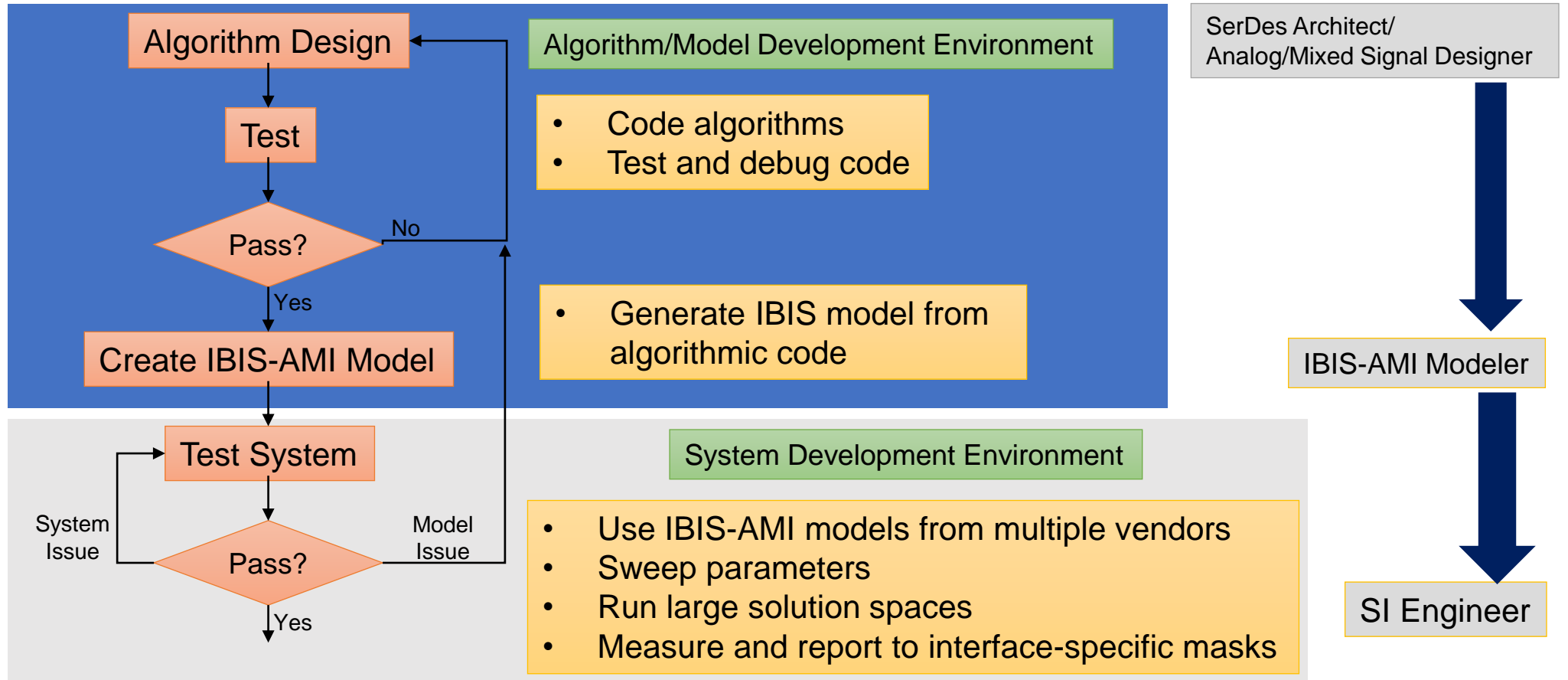
- Serializer Deserializer
 - Send Data and Clock
 - Constant increase in speed (~100Gbps)
 - Special case of Mixed-Signal (DSP+RF)
 - Evaluating Equalization techniques
- Example
 - Ethernet
 - Universal Serial BUS
 - DDR (with CDR)
 - PCI



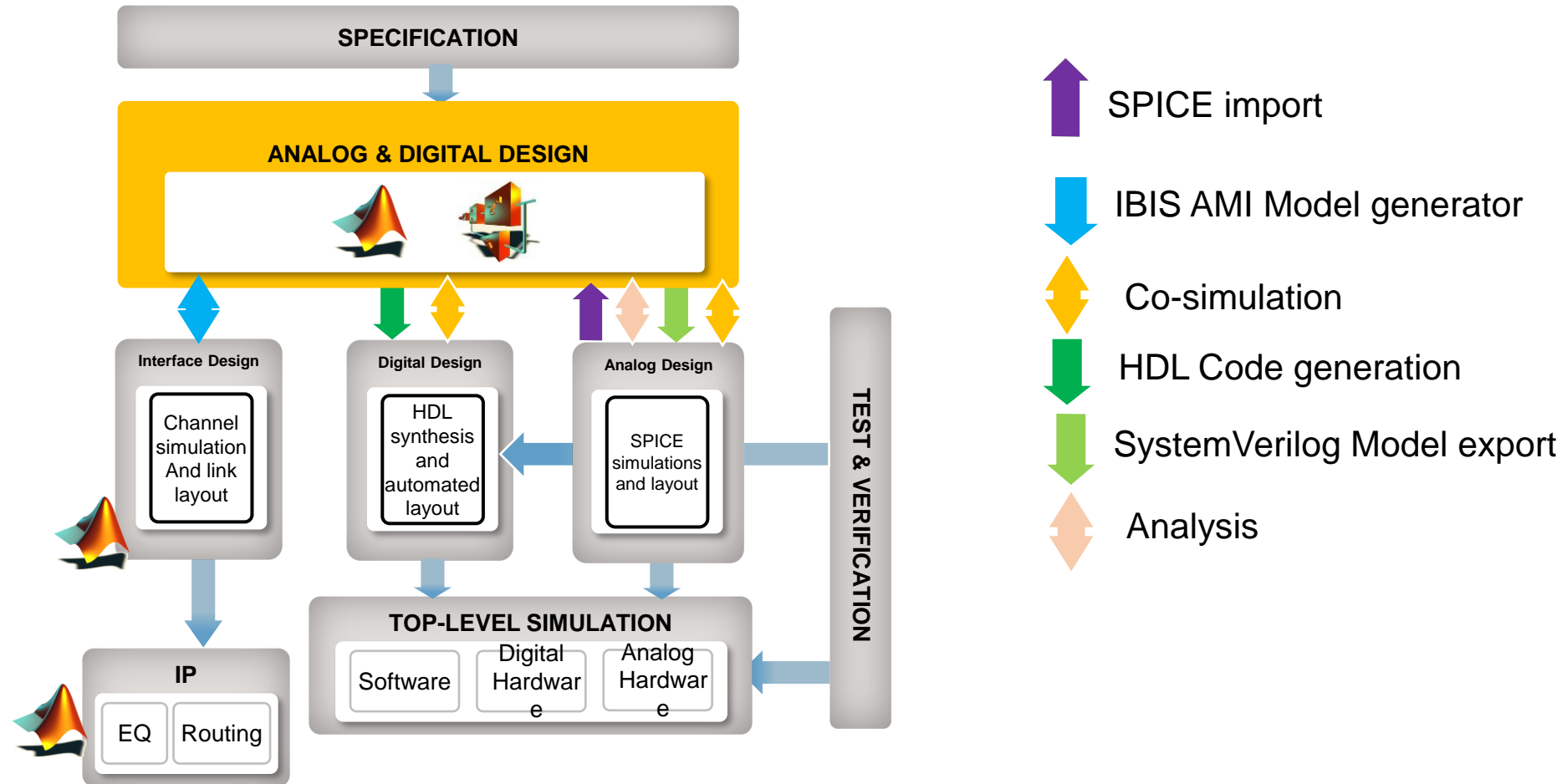
Typical SerDes system: TX, RX and channel



Typical workflow



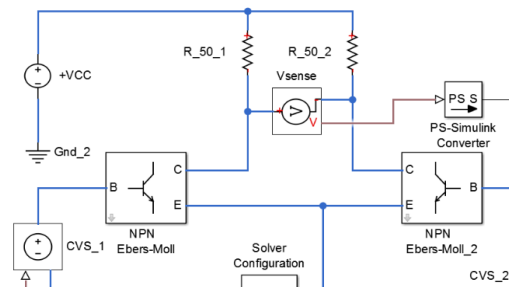
Mixed-Signal Design with MATLAB and Simulink



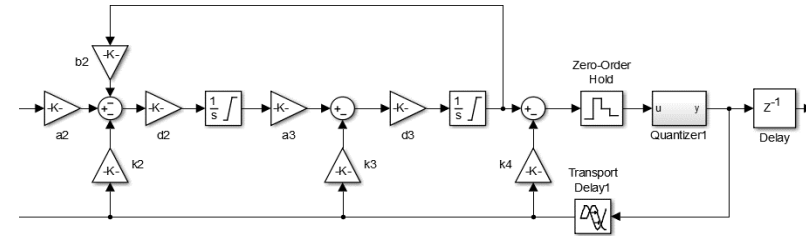
Modeling Approaches

```
206 %% Hemispherical Conformal Arrays
207 % You can also model nonplanar arrays. In many applications, sensors must
208 % conform to the shape of the curved surface they are mounted on. Next is
209 % an example of an antenna array whose elements are uniformly distributed
210 % on a hemisphere.
211 R = 2; % Radius (m)
212 az = -90:10:90; % Azimuth angles
213 el = -80:10:80; % Elevation angles (excluding poles)
214 [az_grid, el_grid] = meshgrid(az,el);
215 poles = [0 0; -90 90]; % Add south and north poles
216 nDir = [poles [az_grid(:) el_grid(:)]]; % Element normal directions
217 N = size(nDir,2); % Number of elements
218 [x, y, z] = sph2cart(deg2rad(nDir(1,:)), deg2rad(nDir(2,:)), R*ones(1,N));
219 ha = phased.ConformalArray('ElementPosition', [x; y; z], ...
220 'ElementNormal', nDir);
221
222 viewArray(ha, 'Title', 'Hemispherical Conformal Array');
223 view(90,0)
224
```

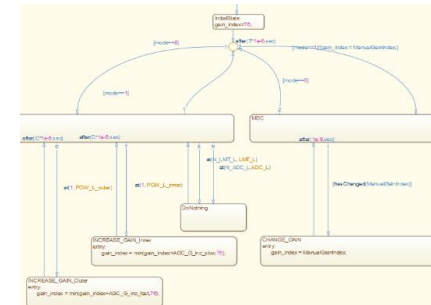
Algorithms



Physical Network



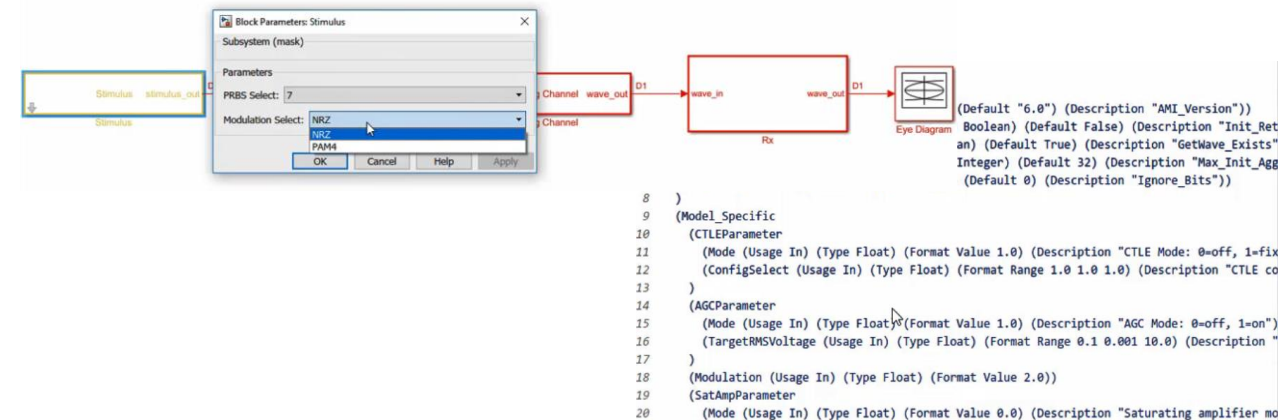
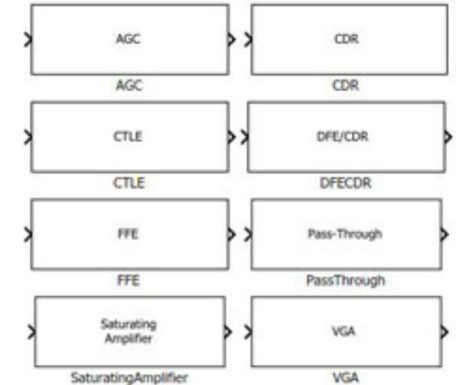
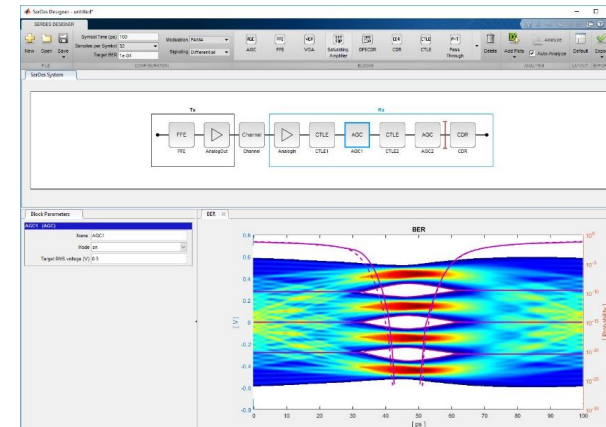
Behavioral Models



Control Logic

System-level modeling workflow

- Design and analyze transmitters and receivers with the SerDes Designer app
- Develop equalization algorithms with MATLAB System objects and Simulink blocks
 - FFE, DFE, AGC, CDR, CTLE, etc...
- Perform SerDes statistical analysis and time-domain simulation
- Generate **dual IBIS-AMI models** for 3rd party channel simulators
- Use reference designs for high-speed links such as Ethernet CEI-56G, DDR5, PCI-Gen4



Starting point: SerDes app

- Modulation
- Sample rate
- Signalling

Add SerDes components

Export to:

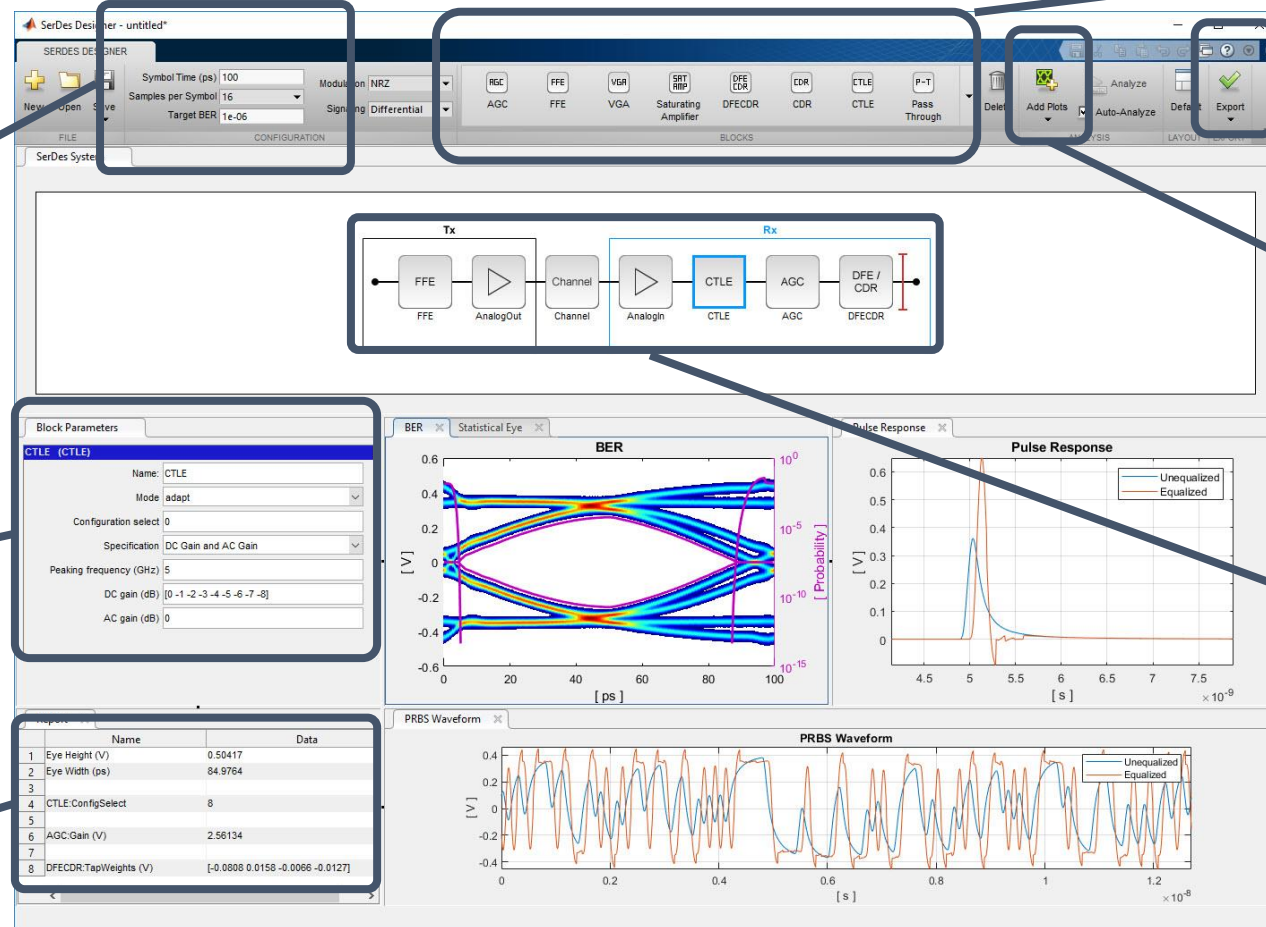
- MATLAB
- Simulink
- IBIS-AMI

Plot analysis results

High-speed link

Component specifications

Report



SERDES DESIGNER

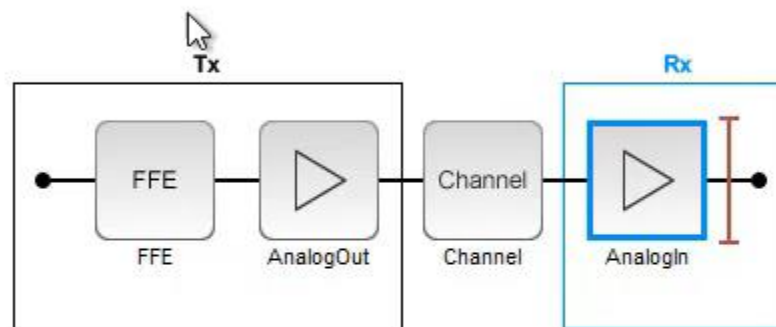
FILE CONFIGURATION BLOCKS ANALYSIS LAYOUT EXPORT

Symbol Time (ps) 100 Modulation NRZ
Samples per Symbol 16 Signaling Differential
Target BER 1e-06

AGC FFE VGA SAT AMP DFE CDR
AGC FFE VGA Saturating Amplifier DFECDR CDR

Delete Add Plots Analyze Auto-Analyze Default Export

SerDes System



Block Parameters

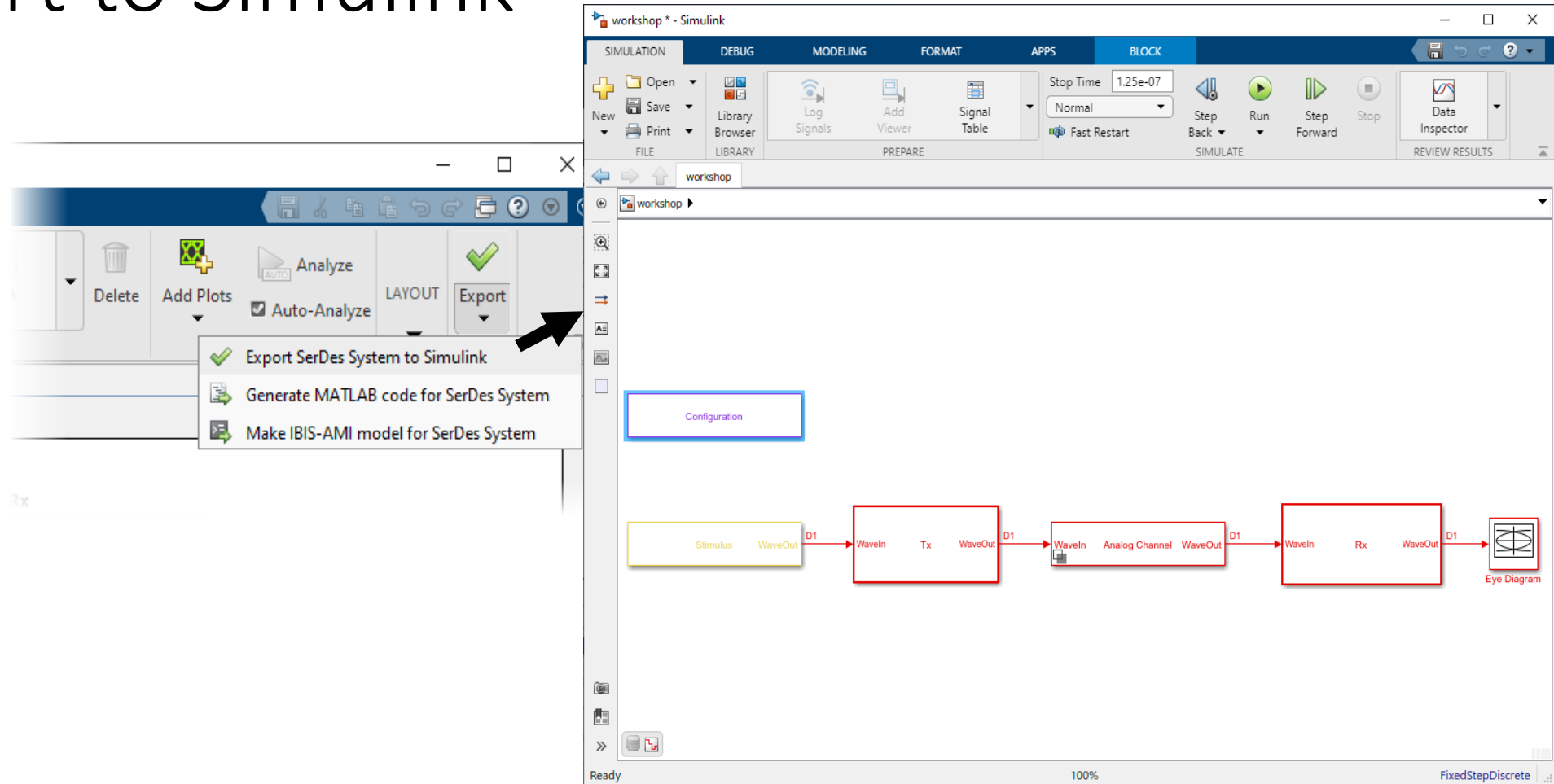
AnalogIn

R (Ohms) 50

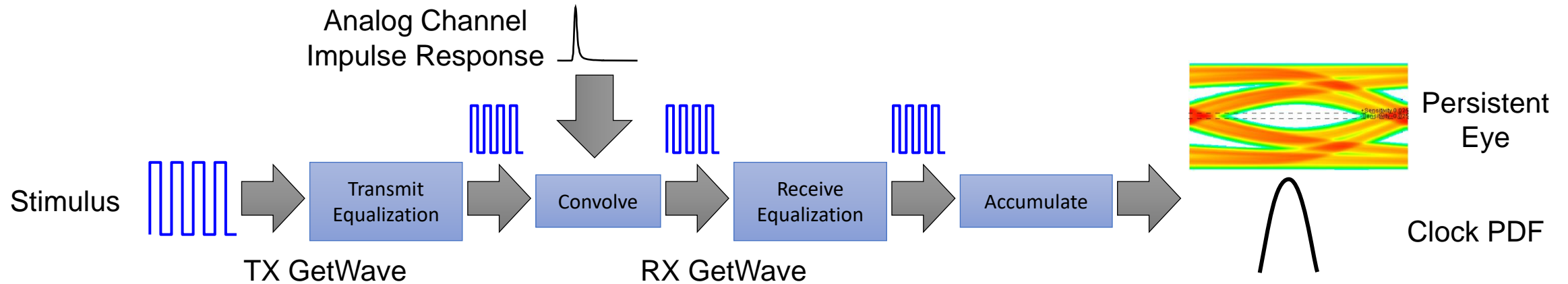
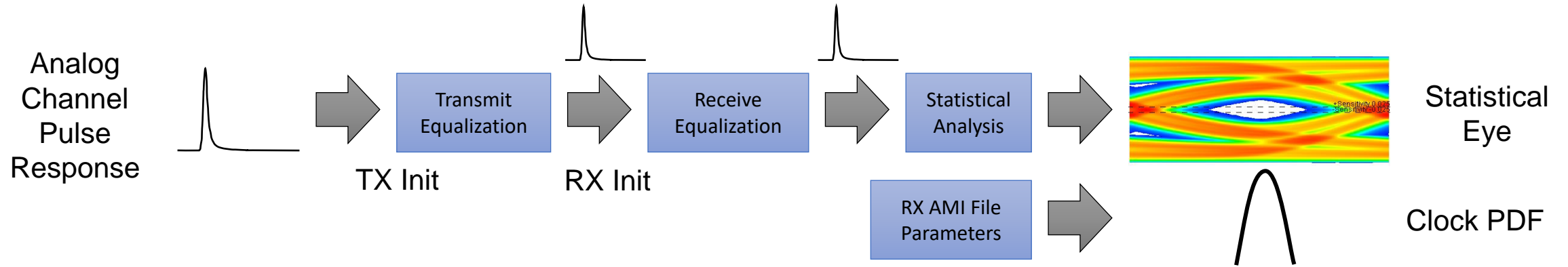
C (pF) 0.2

Plots

Export to Simulink

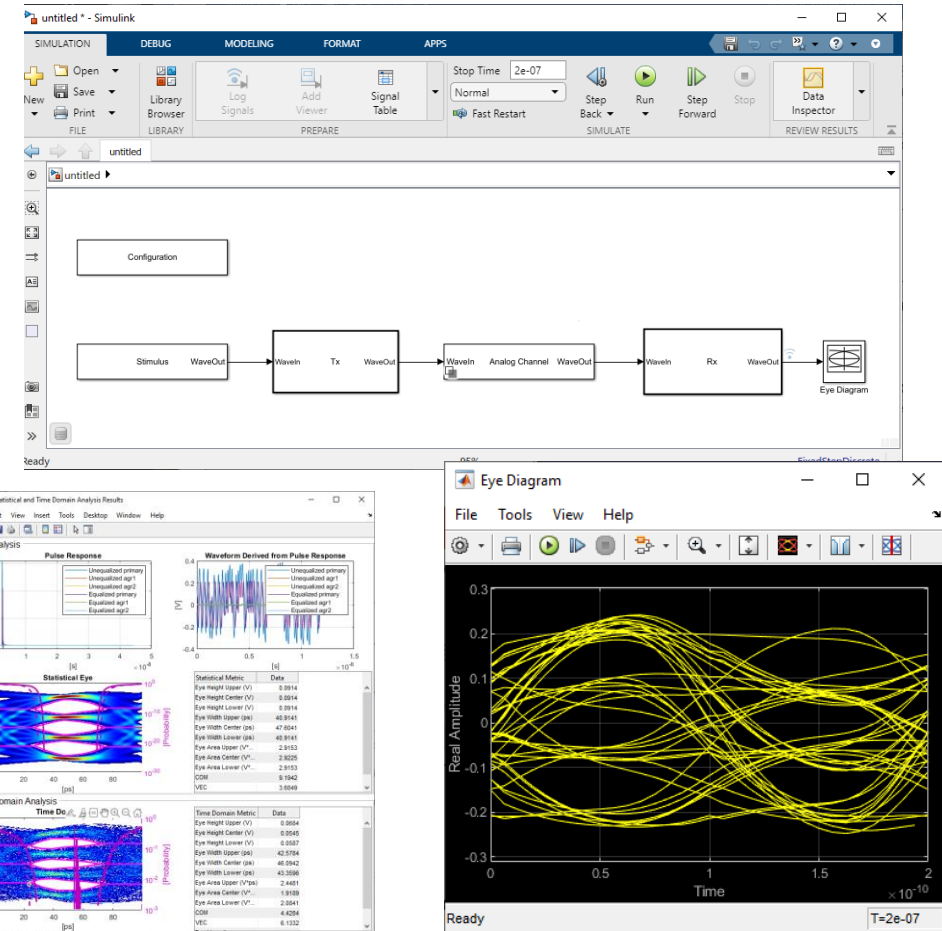


Statistical vs. Time Domain

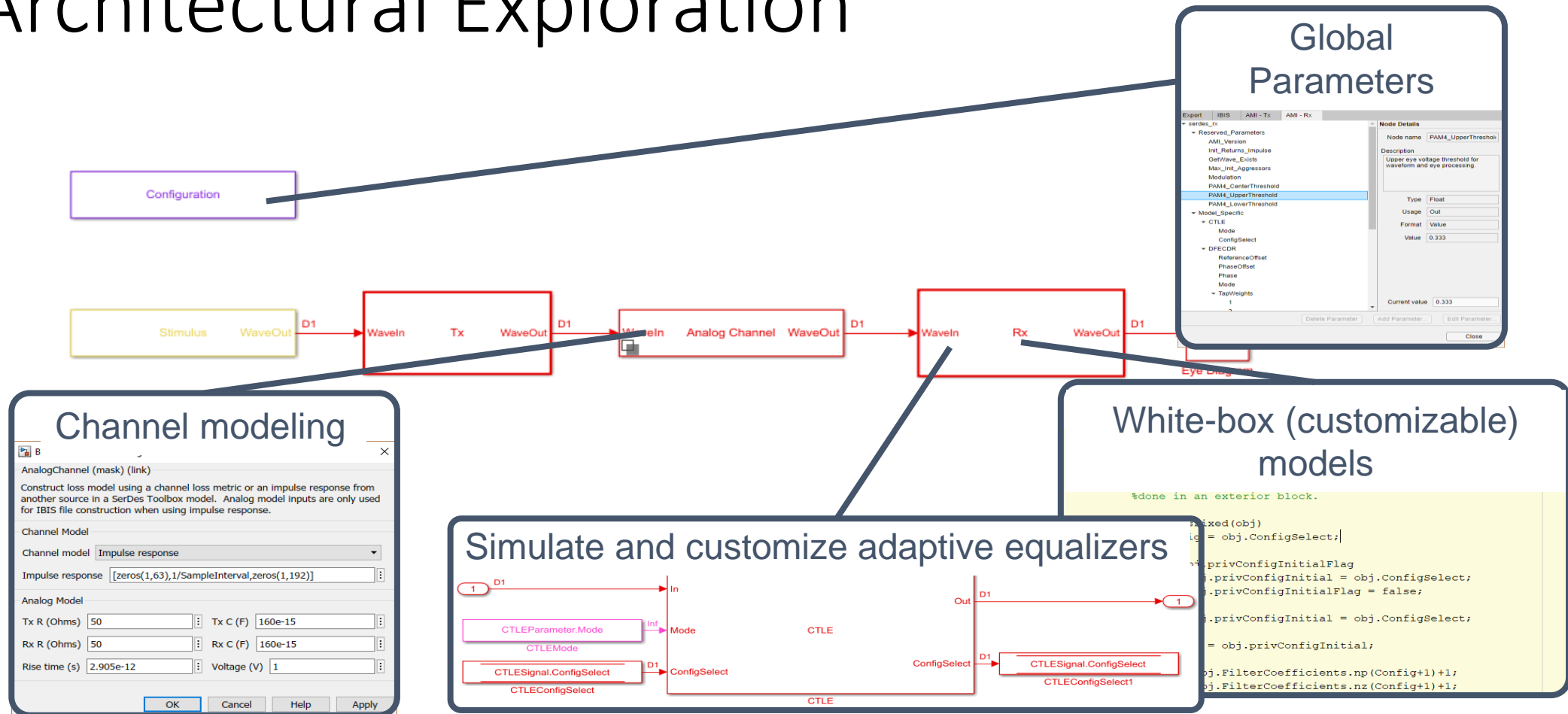


Performance verification

- Export to Simulink models for time-domain simulation
- Model non-linear effects such as saturation
- Customize blocks and equalization algorithms
- Enable global adaptation, and back-channel optimization



Architectural Exploration



Channel & CTLE Modeling

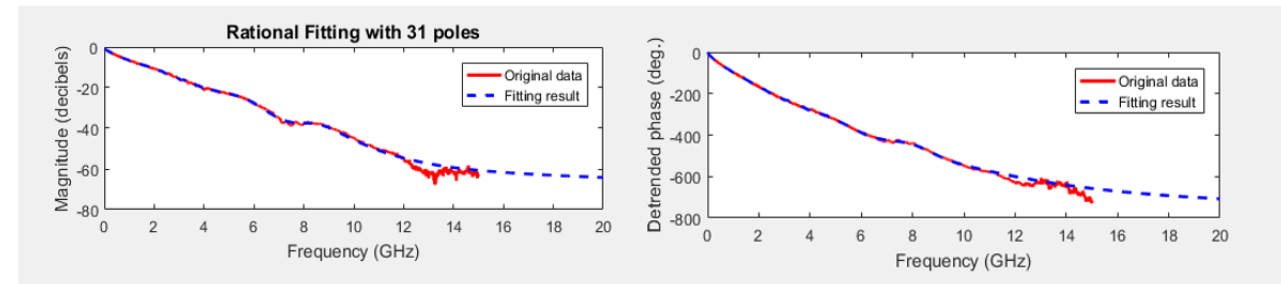
- Manipulate frequency data to extract the desired information
 - Convert single ended **S-parameters**, select port-pair configuration
 - Analyze impedance, attenuation, phase delay
- Use rational fitting for time-domain simulation
 - Analyze and enforce passivity
 - Causal by construction
 - No overfitting of noise
- Analyze impulse response, poles and zeros



$$f(s) = \left(\sum_{k=1}^N \frac{C_k}{s - A_k} + D \right) e^{-st_d}$$

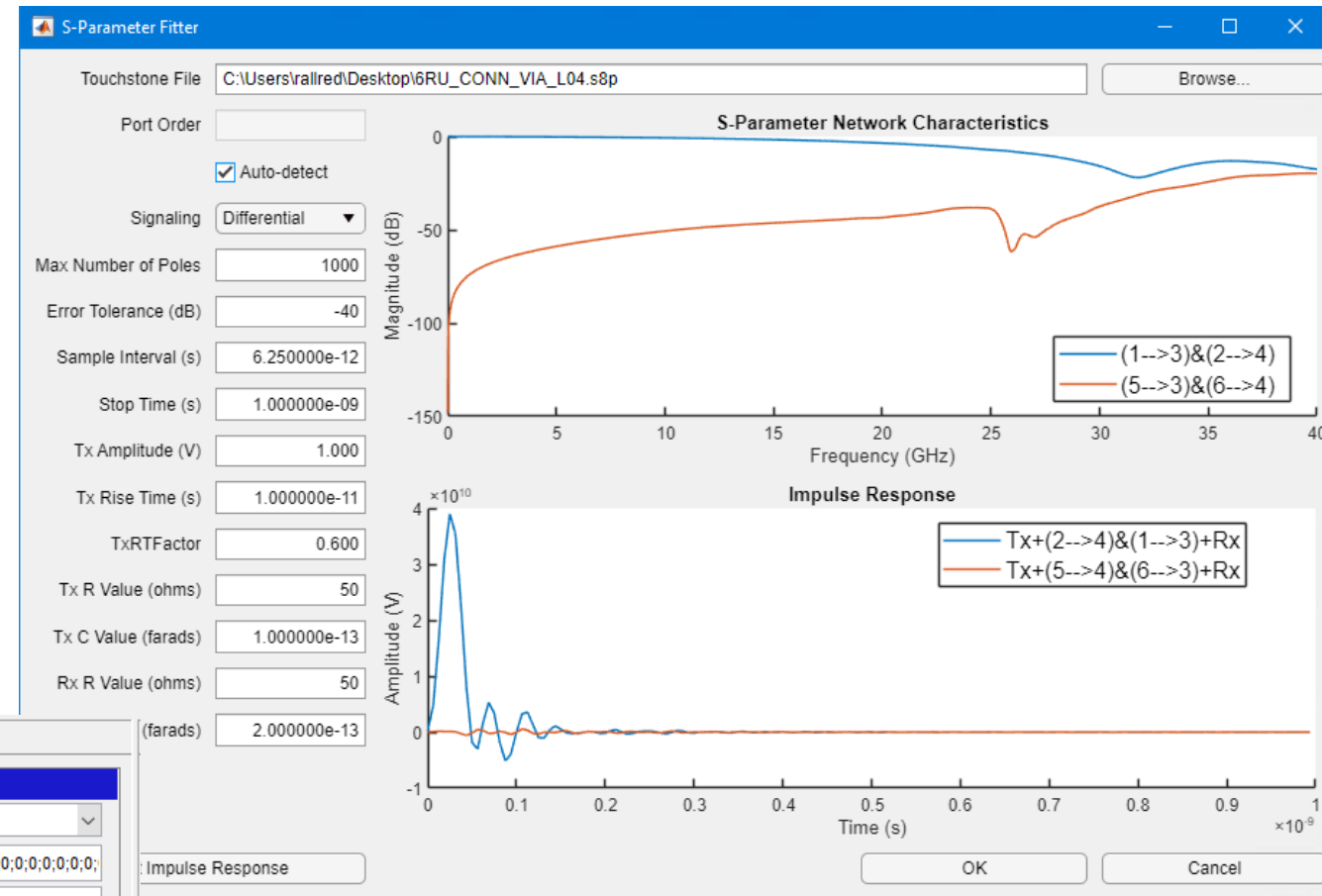
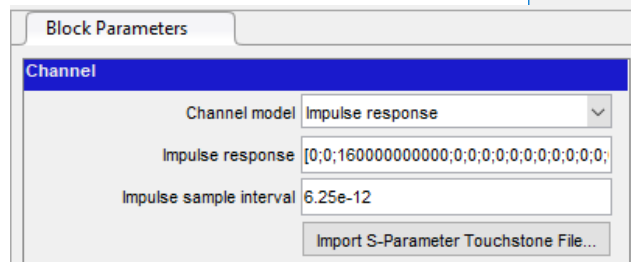
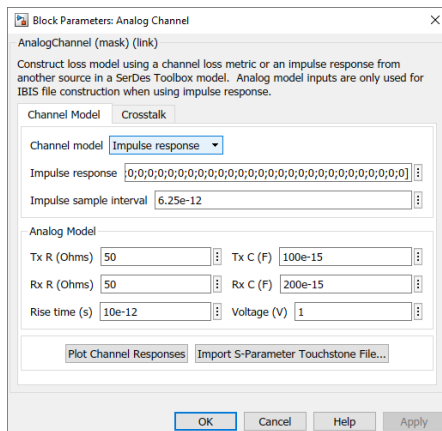
Annotations for the equation:

- Residues**: Points to the coefficients C_k .
- Poles**: Points to the denominator terms $s - A_k$.
- Time delay**: Points to the exponential term e^{-st_d} .
- Direct feedthrough (value at ∞ frequency)**: Points to the constant term D .



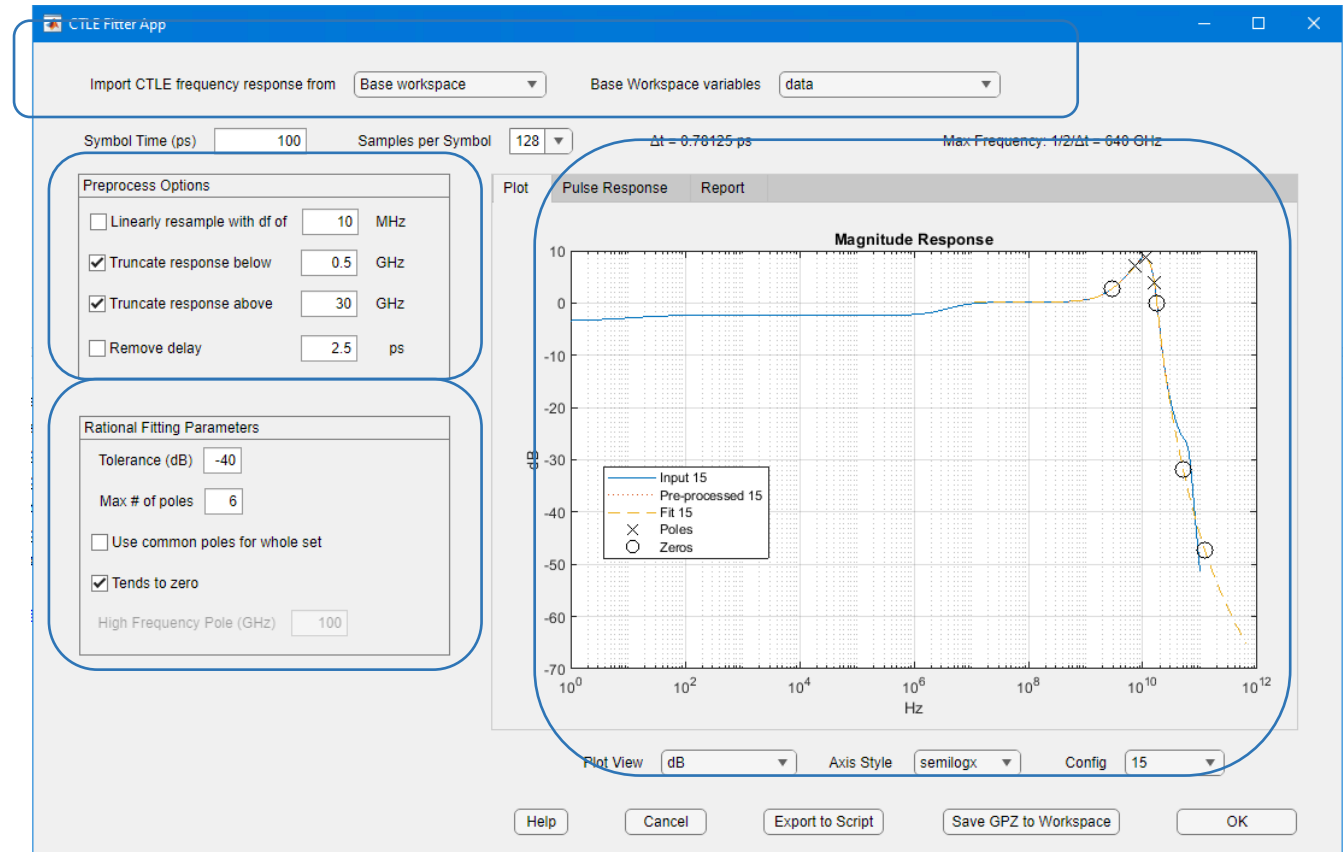
S-Parameter Import

- S-Parameter Fitter App
 - Accessible from SerDes Designer App, Analog Channel block in Simulink, and command line
 - Push button experience customers want!
- S-Parameter Fitter Class enhanced
 - Signal-Ended support (DDR5)
 - Crosstalk support

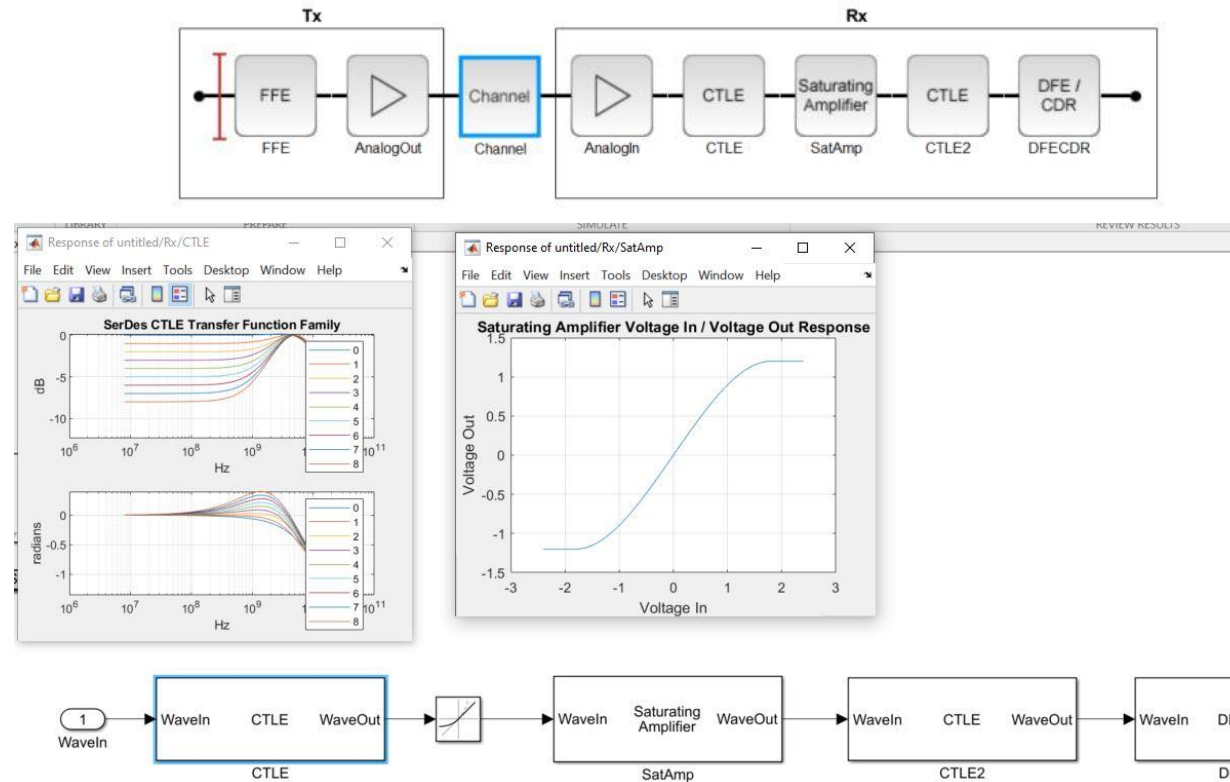


Improved accuracy with bottom-up modeling

- Import Data
- Preprocess Data
- Fit Data
- Visualize Data & Fit
- Integrated with
 - SerDes Designer App
 - CTLE Blocks



Example of inclusion of Non-Linearity



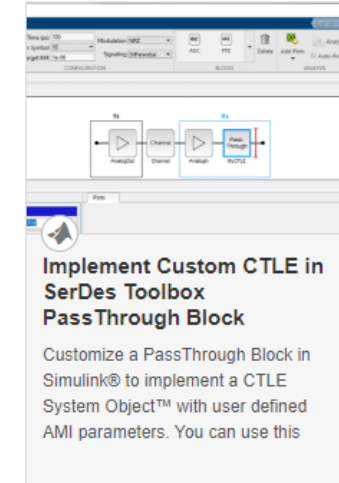
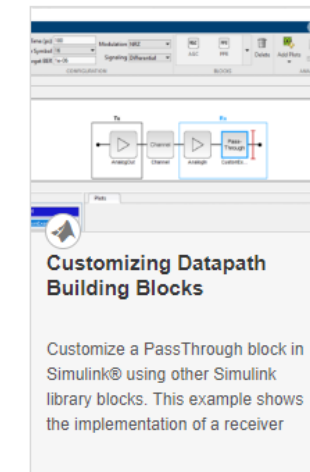
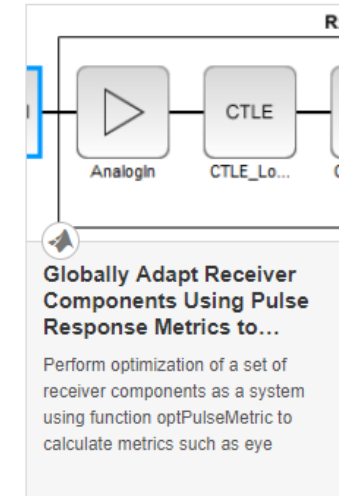
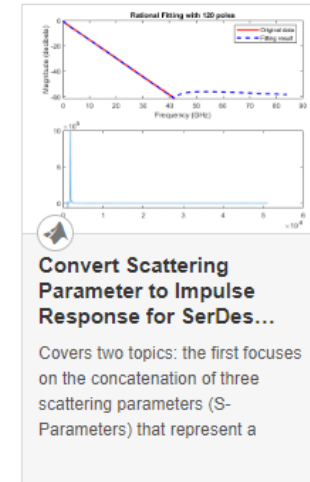
SerDes App

Simulink Export

Rate limiter

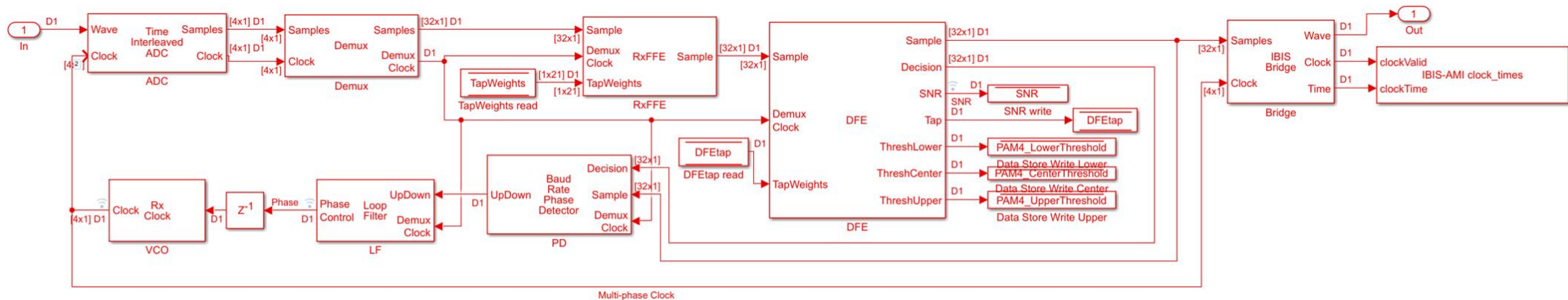
New Examples

- S-Parameter to Impulse Response
- Global Optimization
- Custom Block Workflow – Edit CTLE
- Custom Block Workflow – Use any Simulink block



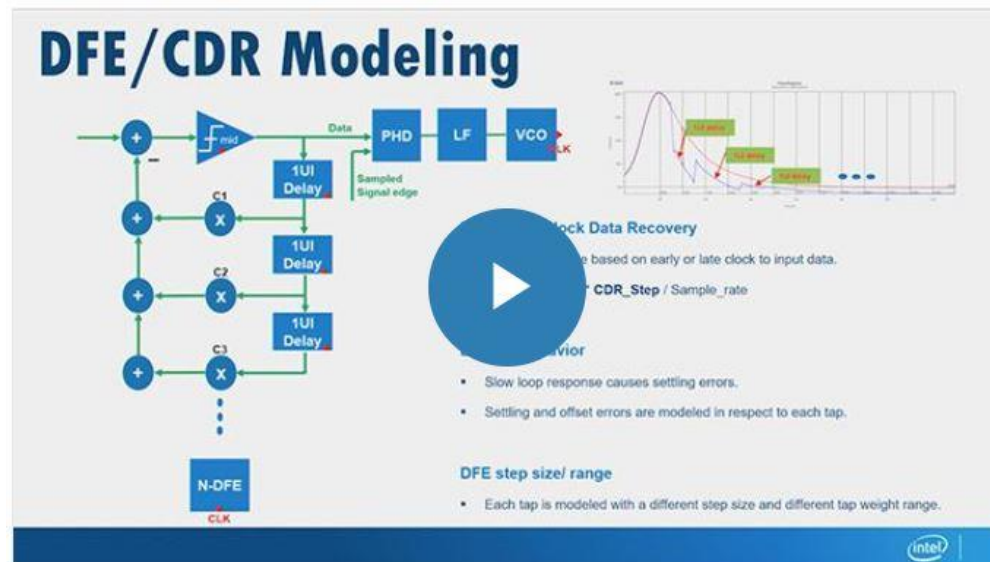
Advanced example for high speeds

- Show how to more precisely **explore the tradeoffs** between:
 - Number of interleaved ADCs
 - Gain, timing, bandwidth and voltage offsets between the interleaved ADCs
 - Demux width
 - DSP adaptation loops



Customer reference: Intel

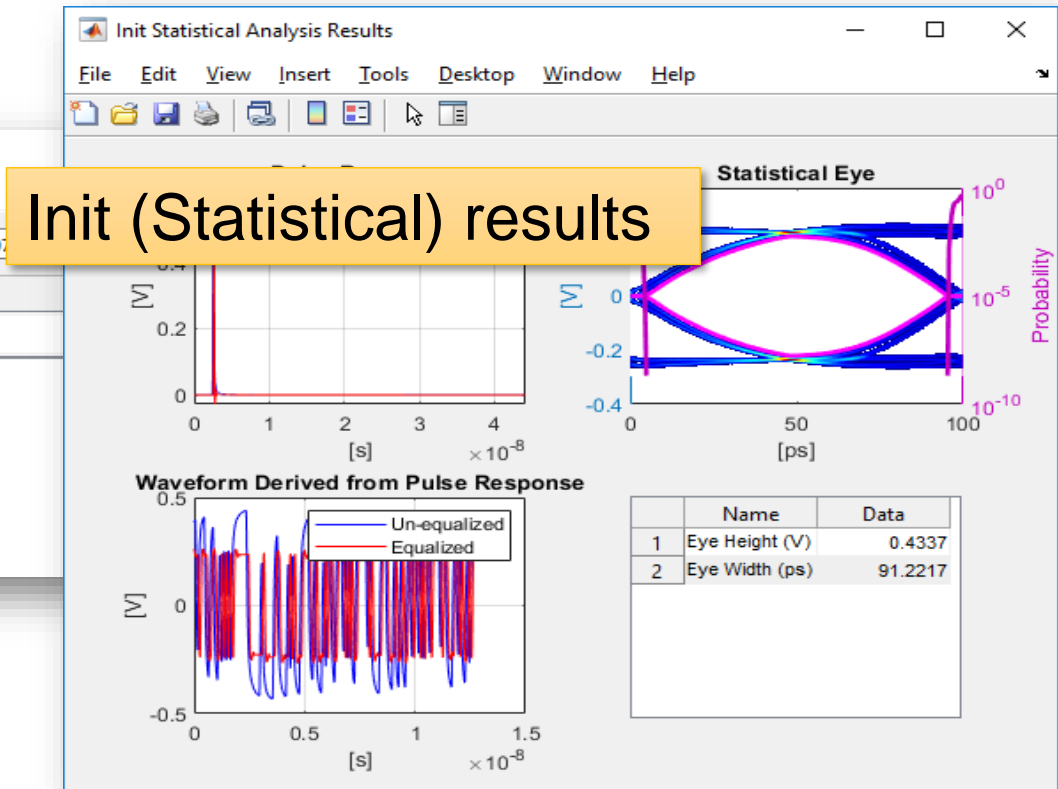
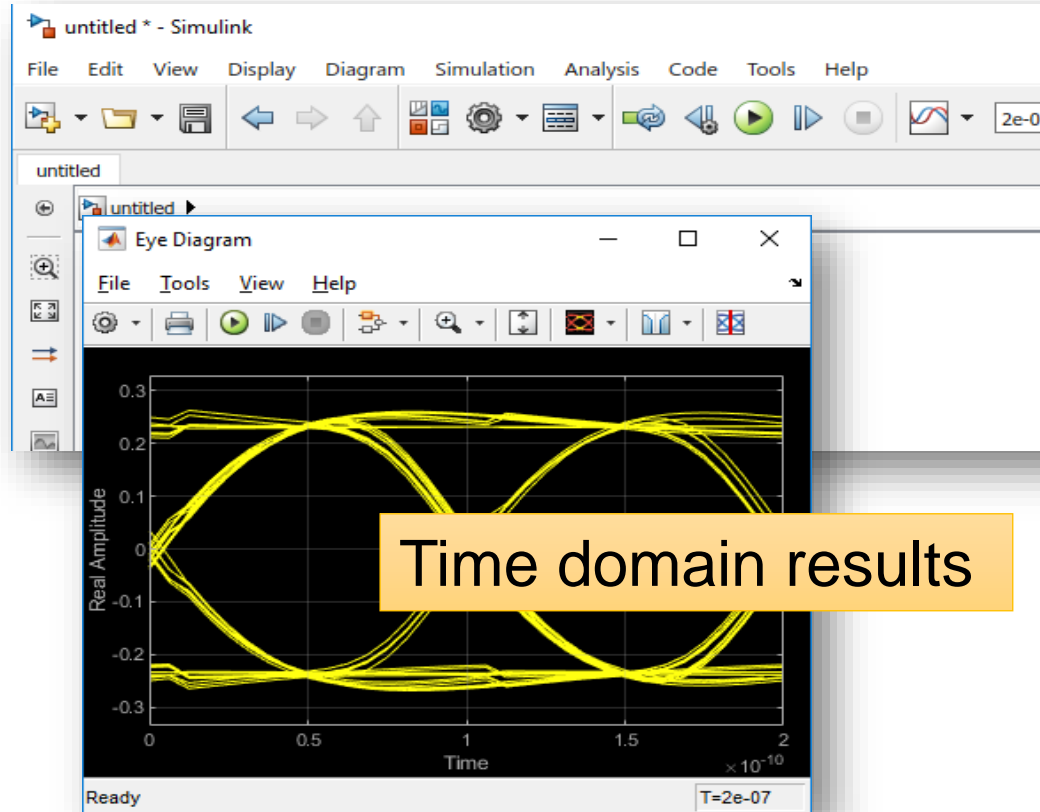
- [56G PAM4 IBIS-AMI Model](#)



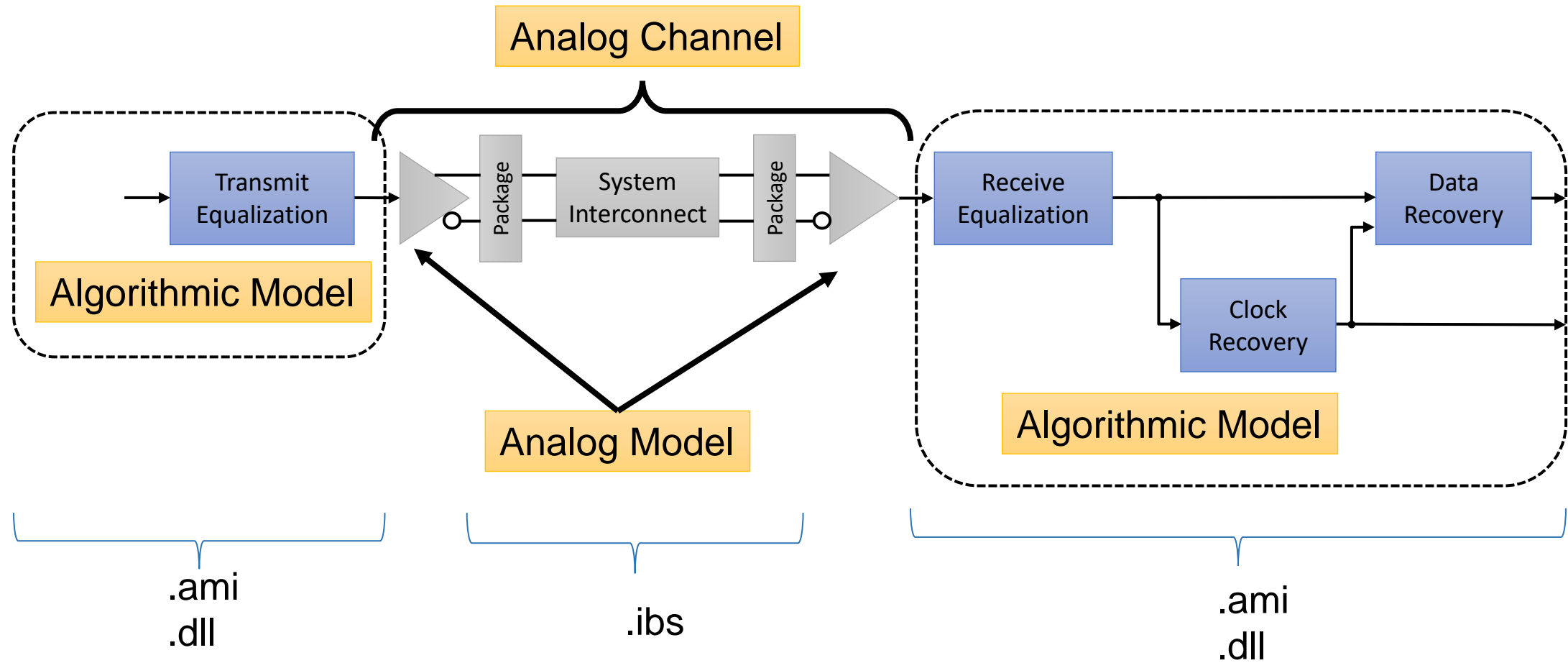
- [DesignCon 2020](#) –

- DfA (Design for AMI) – A New Integrated Workflow for Modeling 56G PAM4 SerDes Systems

Correlated Simulations

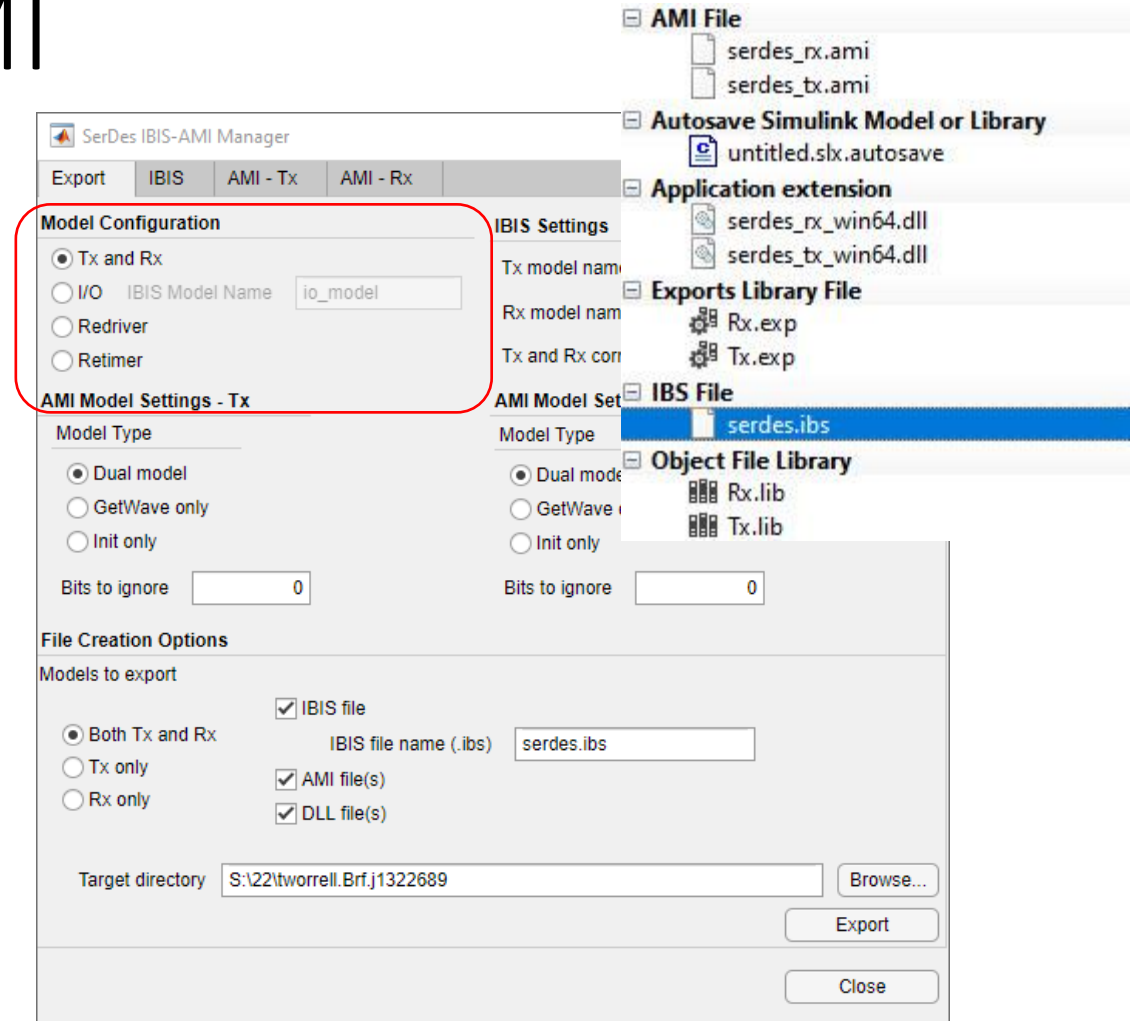


Generation of IBIS-AMI

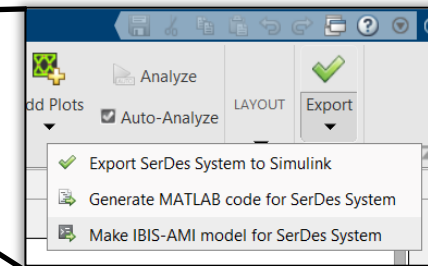
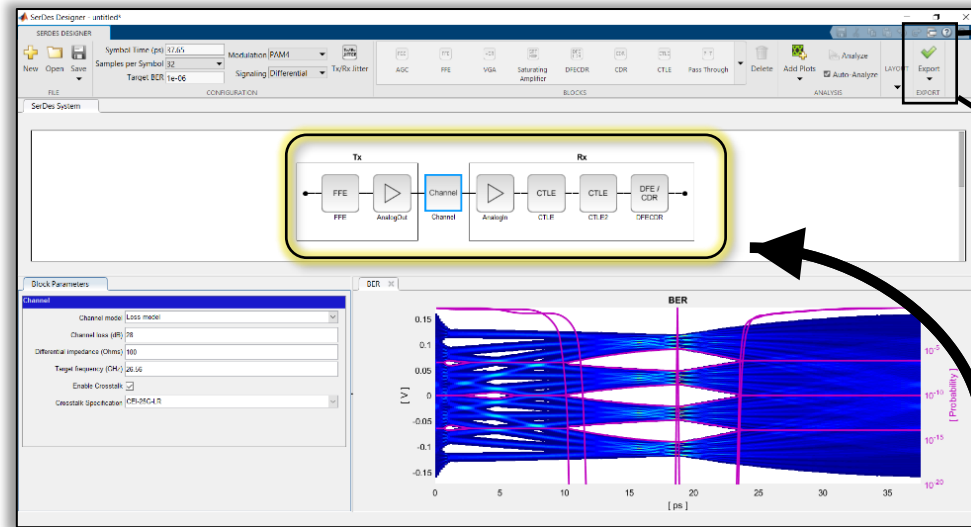


Generation of IBIS-AMI

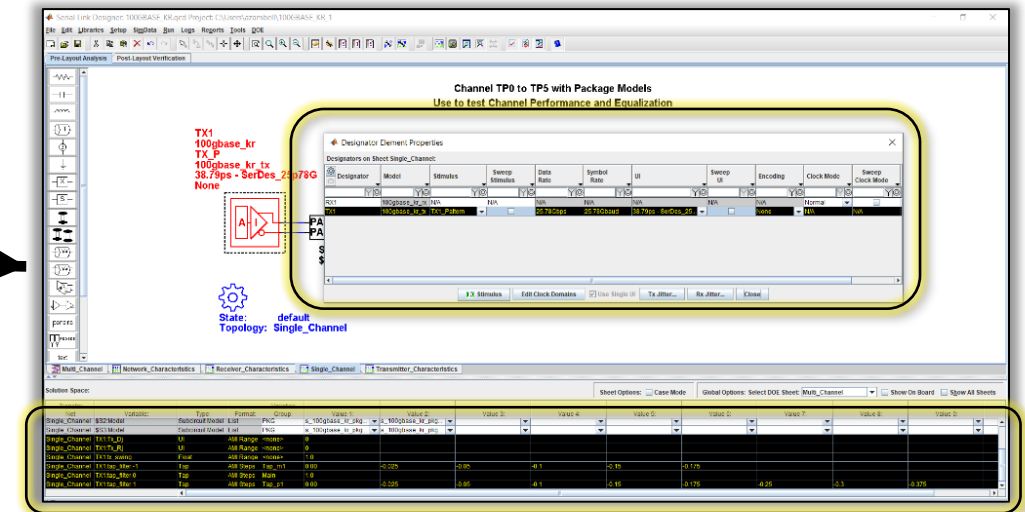
- Generate standard-compliant Init and GetWave IBIS-AMI models
- Generate associated analog IBIS model
- Customize the model interface by managing the IBIS-AMI-parameters
- Retimer & redriver:
 - Connects Rx to Tx per IBIS-AMI spec
- I/O: Bi-directional for DDR applications



Integration for testing

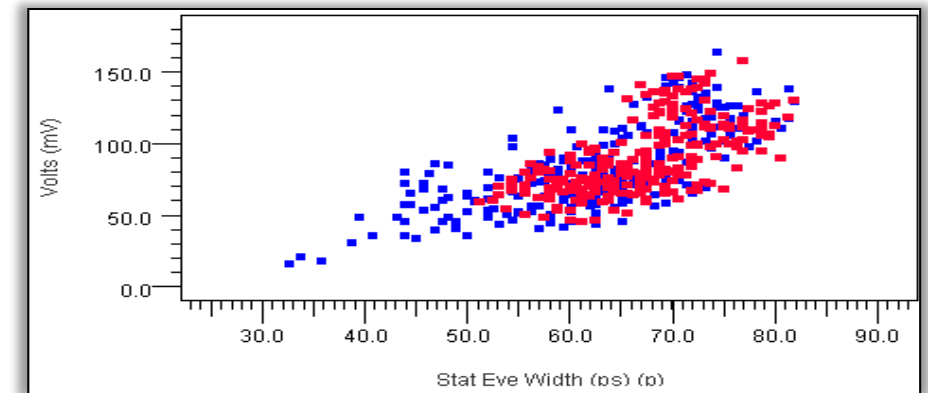
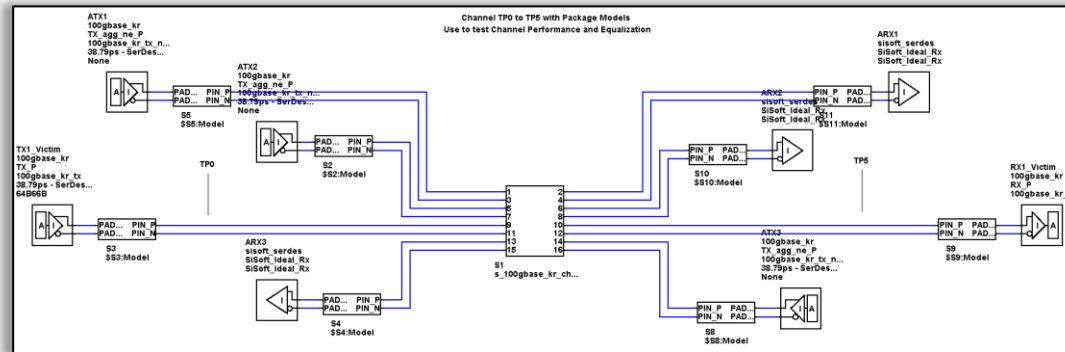


- Build your model in SerDes Toolbox and export an IBIS-AMI model directly into Signal Integrity Toolbox for Regression Analysis
- Sweep your IBIS-AMI model parameters to test them with various channels in Signal Integrity Toolbox
- If there are any issues, the test case can be pushed back to SerDes Toolbox / Simulink where you have full debug capabilities



Verifying the IBIS-AMI model with the channel

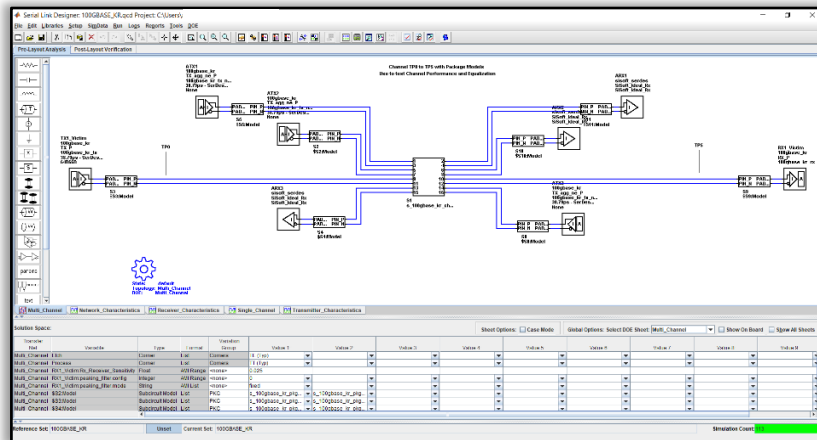
- Sweep parameters to explore the to find the best solution
- Build schematics to test the signal integrity of high-speed end-to-end serial and parallel links
- Test components and/or system designs for industry standard compliance
- Perform channel, statistical, and time-domain analyses and visualize the results
- Import PCB files for post-layout verification
- Import IBIS-AMI models for testing



Pre-layout Analysis workflow

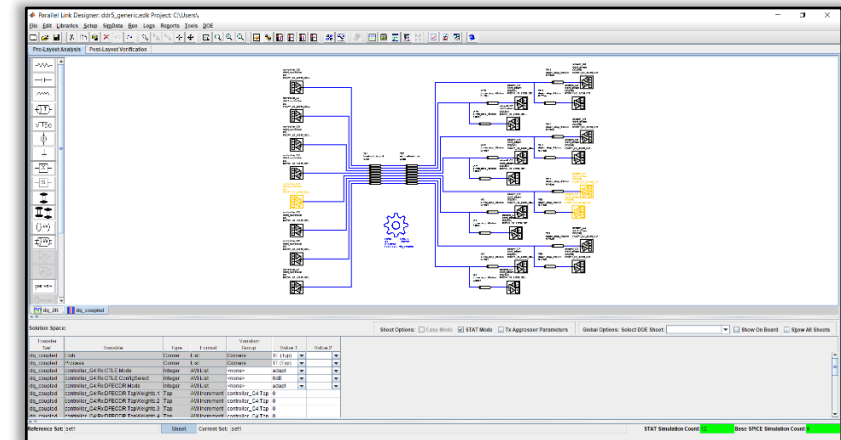
• Serial Link

- Determine optimal equalization settings
- Predict operating margins and bit error rates
- Perform network, statistical, and time-domain analysis



• Parallel Link

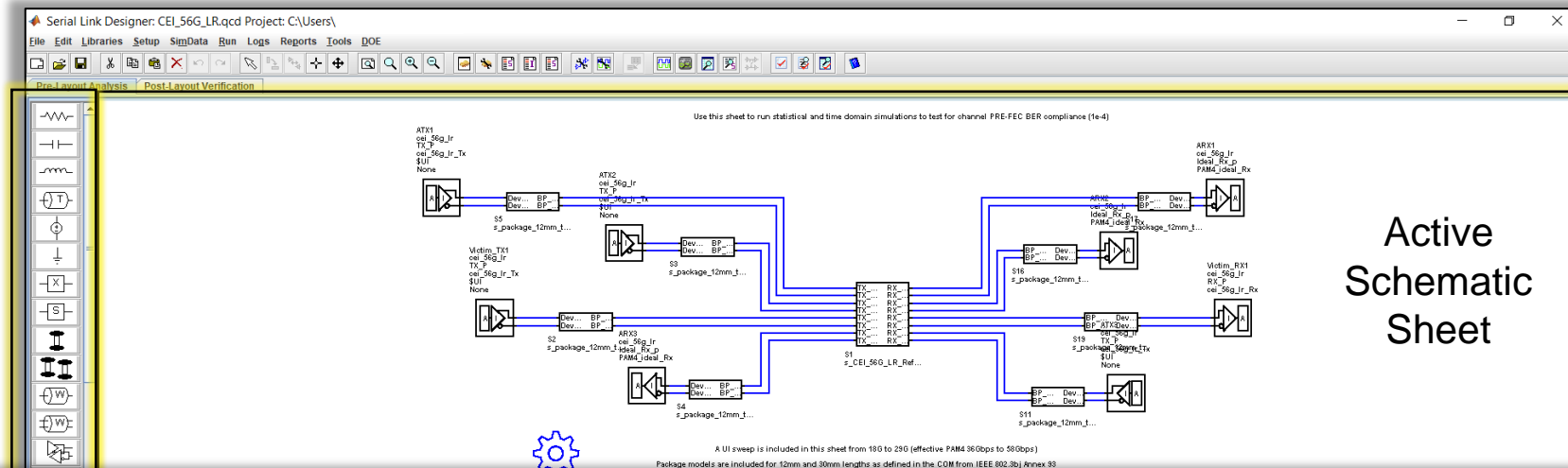
- Determine setup/hold timing and voltage margins
- Conduct waveform and timing analysis
- Analyze interfaces for timing and signal integrity compliance



Pre-layout Analysis: solution space

List of
Elements

All
Schematic
Sheets

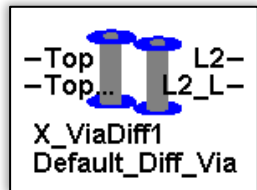


Active
Schematic
Sheet

	35.17ps - SerDes_28...	38.46ps - SerDes_26...	41.67ps - SerDes_24...	45.45ps - SerDes_22...	50.0ps - SerDes_20...	55.55ps - SerDes_18...
55.55ps - SerDes_18.0G						
50.0ps - SerDes_20.0G						
45.45ps - SerDes_22.0G						
41.67ps - SerDes_24.0G						
38.46ps - SerDes_26.0G						
35.17ps - SerDes_28.0G						
34.48ps - SerDes_29.0G						
Multi_Channel_BER_Compliance	Victim_RX1.Modulation	String	AMI List	<none>	PAM4	
Multi_Channel_BER_Compliance	Victim_RX1.AGC.Mode	String	AMI List	<none>	Off	
Multi_Channel_BER_Compliance	Victim_RX1.AGC.Level	Float	AMI Range	<none>	0.3	
Multi_Channel_BER_Compliance	Victim_RX1.Rx_Sj	UI	AMI Range	<none>	0	
Multi_Channel_BER_Compliance	Victim_RX1.peaking_filter.mode	String	AMI List	<none>	auto	
Multi_Channel_BER_Compliance	Victim_RX1.peaking_filter.conf	Integer	AMI Range	<none>	0	
Reference Set: Default	Unset	Current Set: Default				Simulation Count: 1

Solution
Space

Building schematic: Configure Via



Via Editor

File Edit

Library = Stackup default.stkup + Pre-Layout Vias

Cursor: (-35.0, 2)

Zdiff = 65.5 Ohms
Zcm = 22.7 Ohms
Delay = 11.2 ps
Top Stub = 0.0 s
Bottom Stub = 0.0 s
Cpad = 23.0 fF
Exit Trace = 55.0 mils

Via Model Name: Default_Diff_Via

Copy Rename Delete

Geometry

Start Layer: Top
End Layer: Bottom
Finished Hole Diameter: 18.0 mils
Drilled Hole Diameter: 21.0 mils

Pad Antipad Racetrack

Shape: Circle Circle
Diameter: 30.0 50.0
Width: 30.0 50.0 110.0
Height: 30.0 50.0 50.0

Pads On All Layers
☒ Differential Via Spacing: 60.0 mils
☒ Racetrack

Back Drill

☒ Enable ☐ By Stub ☐ By Layer ☒ By Depth

Drill Side	Stub (mils)	Layer	Depth (mils)
Top	0.0		0.0
Bottom	0.0		0.0

Model Override

☐ Enable

File Subcircuit

Create Edit Clear

Board Height = 64.2mils Selected Layer(s) Thickness = 0.0mils Edit Stackup

ID	Layer Name	Type	Thickness (mils)	Left Via Connect	Left Via X Section	Right Via X Section	Right Via Connect
1	Dielectric	1.0					
2	Top	Signal	0.6	<input checked="" type="checkbox"/>			<input checked="" type="checkbox"/>
3	Dielectric	5.0					
4	P1	Plane	0.6				
5	Dielectric	5.0					
6	L2	Signal	0.6				
7	Dielectric	5.0					
8	P2	Plane	0.6				
9	Dielectric	5.0					
10	L3	Signal	0.6				
11	Dielectric	5.0					
12	P3	Plane	0.6				
13	Dielectric	5.0					
14	P4	Plane	0.6				
15	Dielectric	5.0					
16	L4	Signal	0.6				
17	Dielectric	5.0					
18	P5	Plane	0.6				
19	Dielectric	5.0					
20	L5	Signal	0.6				
21	Dielectric	5.0					
22	P6	Plane	0.6				
23	Dielectric	5.0					
24	Bottom	Signal	0.6	<input checked="" type="checkbox"/>			<input checked="" type="checkbox"/>
25	Dielectric	1.0					

Building schematic: Configure Transmission Line

Lossy Transmission Line Editor

File Edit

Transmission Line Model = diff_strip_97ohm_2x.mod (Library Model)

☐ Single Conductor ☒ Differential

☒ Coupled Aggressors: 2 Conductors: 6

Model Type

☐ Simple Lossy T-Line

☐ Microstrip

☐ Buried Microstrip

☒ Stripline

Calculate

View Model

Save Save As Close

Reference Plane

Aggressors

Diff Pair L1

R1 Diff Pair

Victim

Dielectric Er

Trace

W

T

H1

H2

Reference Plane

Etch Shape

☐ Rectangle

☒ Trapezoid

Angle (45 - 90 degrees)

Top Width (mils)

67.5

3.4615223

Tabbed Routing

☐ Enable

Tab Pitch (mils)

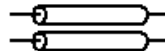
Tab Top Width (mils)

Tab Base Width (mils)

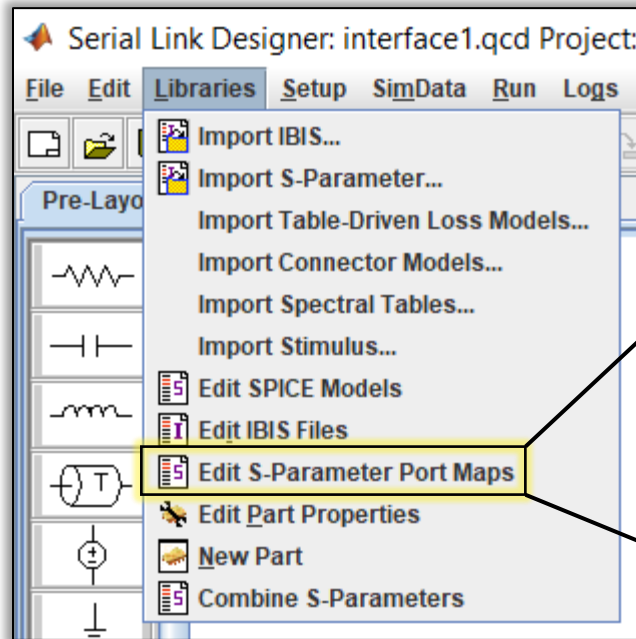
Tab Height (mils)

Coupling Configuration	Differential Impedance(Ohms)	Tpd (ps/in)	Resistance (mOhms/in)	Inductance (nH/in)	Capacitance (pF/in)	Conductivity (Meg S/m)	Trace Width (mils)	Trace Thickness (mils)	Dielectric Height (H1 in mils)	Dielectric Height (H2 in mils)	f (GHz)	Er at f	Loss Tangent	Table-Driven Loss Model	Differential Separation (mils)	Conductor Roughness (Microns)	Aggressor L1 Clearance (mils)	Aggressor R1 Clearance (mils)
Adjacent	94.362	178.141	279.916	11.204	2.893	58.0	4.0	0.65	6.5	13.0	1.0	4.25	0.02	None	4.0	0.15	4.0	4.0

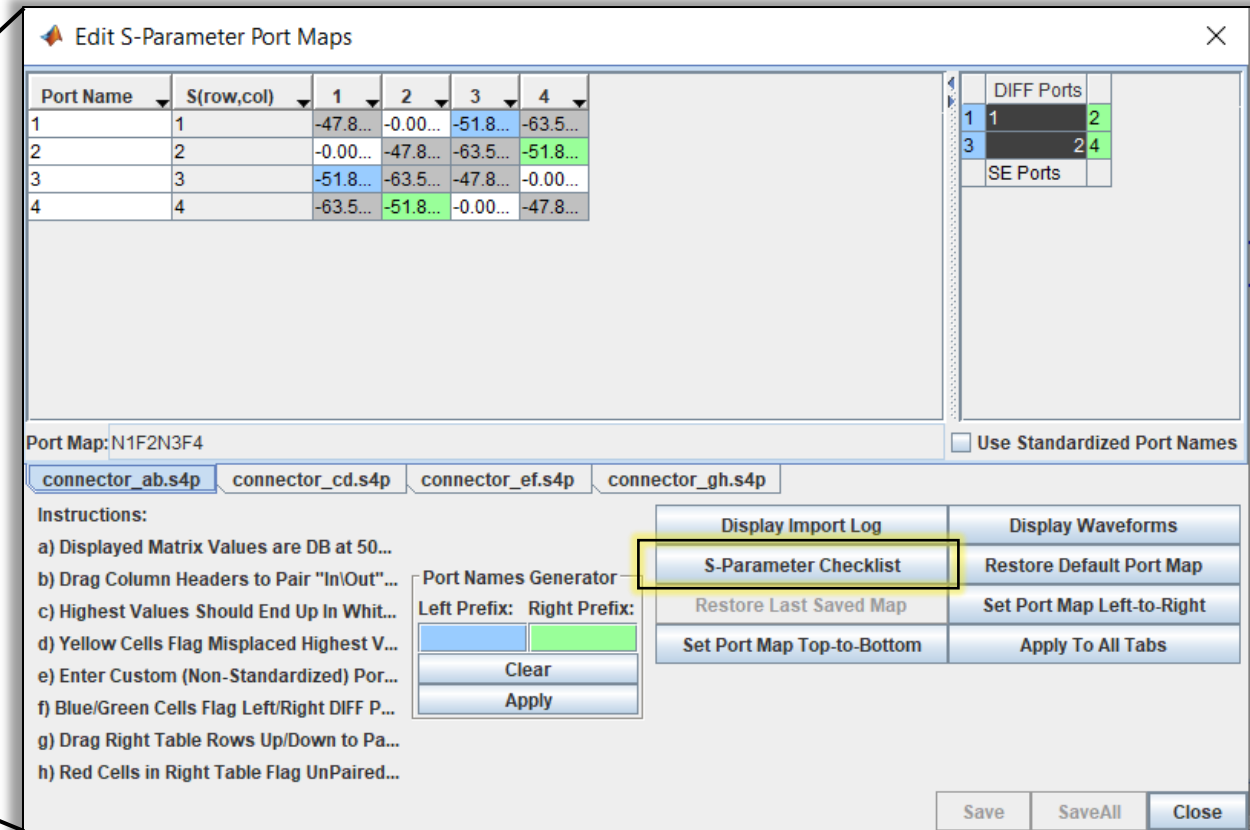
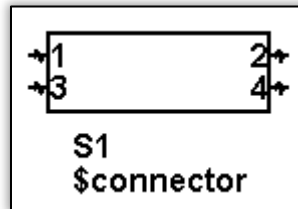
W1
diff_strip_100oh...
\$bp_len



Importing and Edit s-parameter Models

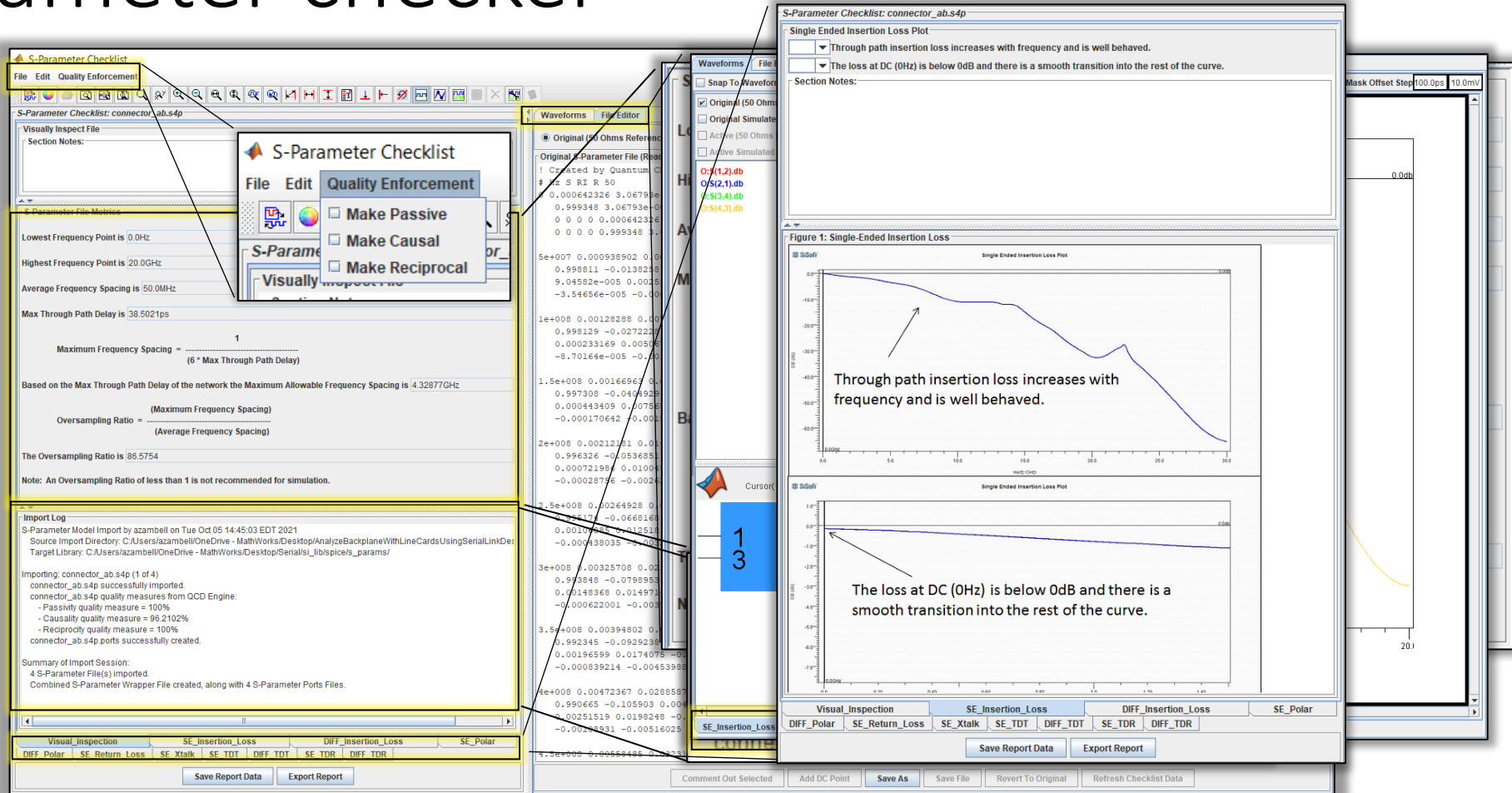


Import and manage various types of models

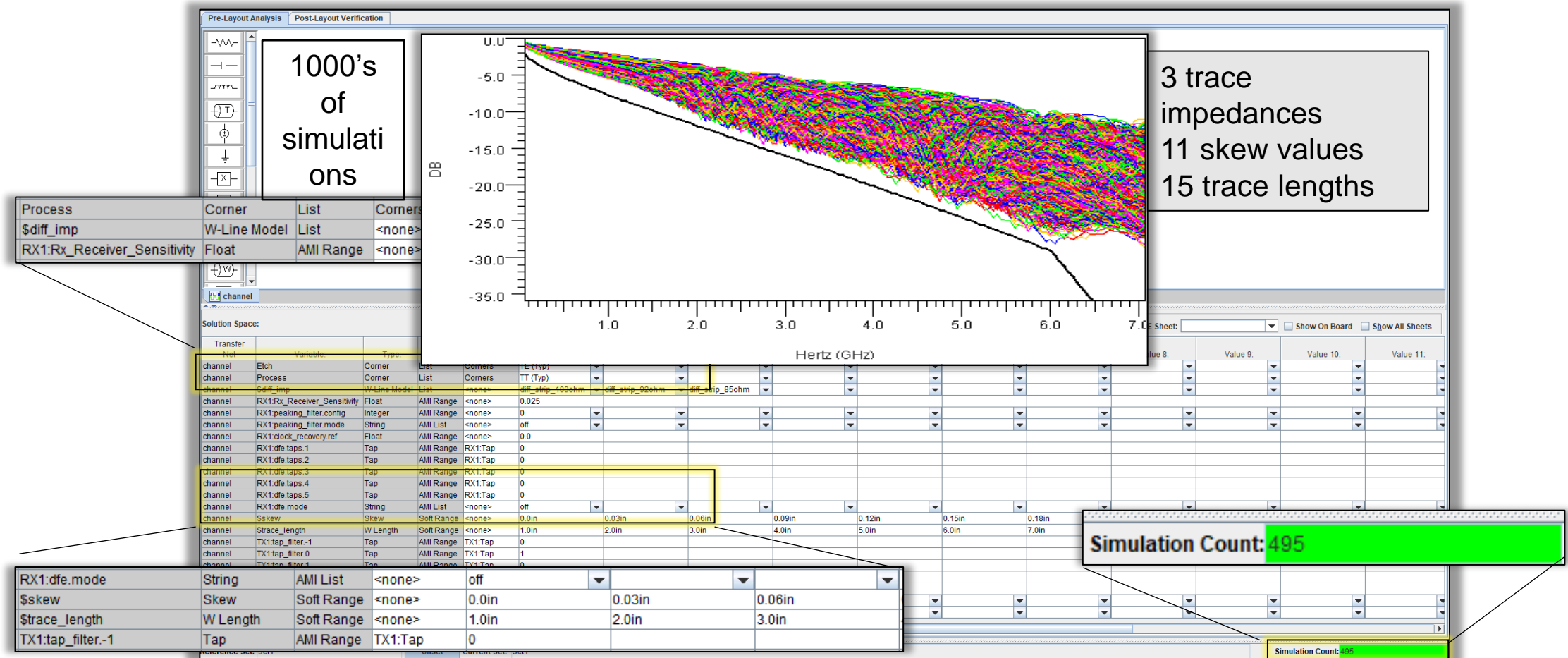


When importing S-Parameters, use the S-Parameter Checklist to verify their quality before use

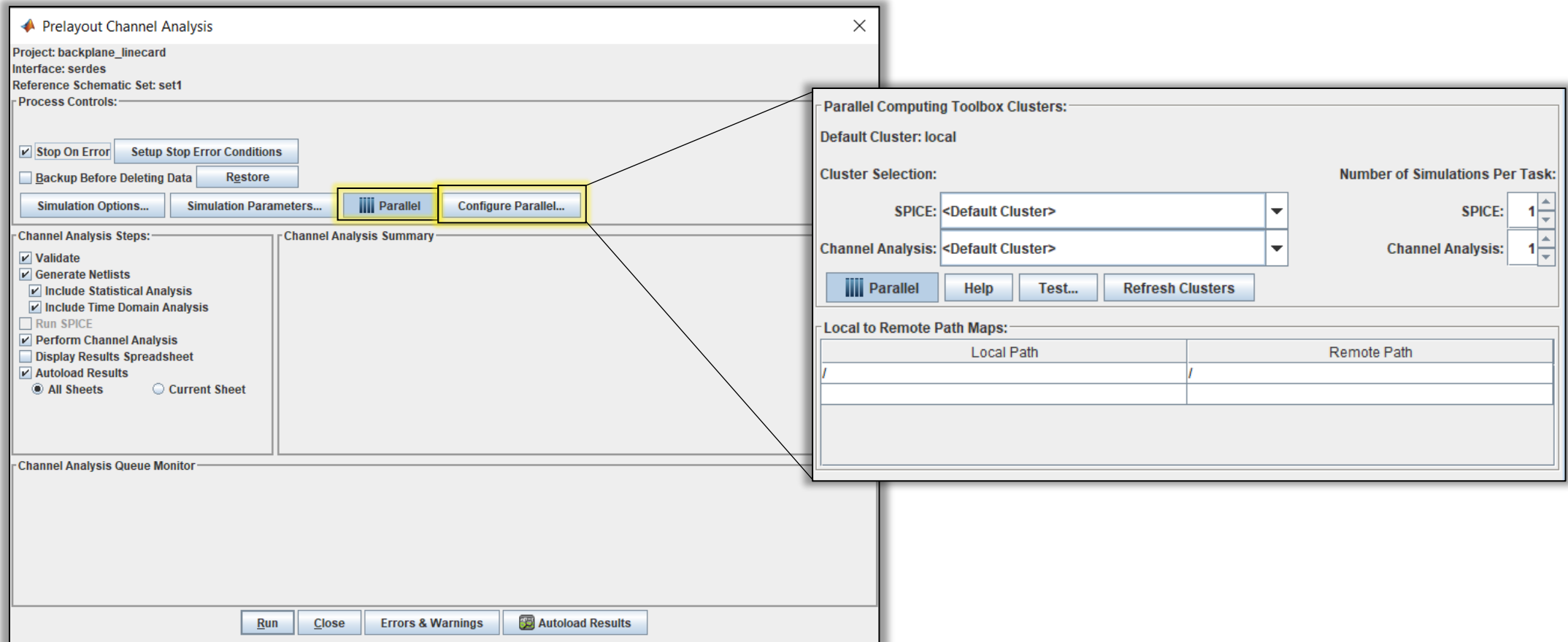
S-parameter checker



Design Space Exploration – Sweep parameter



Design Space Exploration - Parallelization



Design Kit for Industry Standards

Industry Standard Signal Integrity Kits — Examples

PCIe-5 Compliance Kit
Test the compliance of simulation models and topologies to the PCI Express generation 5 (PCIe-5) specification.

PCIe-4 Compliance Kit
Test the compliance of simulation models and topologies to the PCI Express generation 4 (PCIe-4) specification.

PCIe-3 Compliance Kit
Test the compliance of simulation models and topologies to the PCI Express generation 3 (PCIe-3) specification.

PCIe-2 Compliance Kit
Test the compliance of simulation models and topologies to the PCI Express generation 2 (PCIe-2) specification.

CEI 56G-VSR Compliance Kit
Characterize and validate the performance of a CEI 56G-VSR channel design.

CEI 56G-LR Compliance Kit
Characterize and validate the performance of a CEI 56G-LR channel design.

CEI 28G-VSR Compliance Kit
Characterize and validate the performance of a CEI 28G-VSR channel design.

CEI 25G-LR Compliance Kit
Characterize and validate the performance of a CEI 25G-LR channel design.

10GBASE-KR4 Compliance Kit
Characterize and validate the performance of a 10GBASE-KR4 channel design.

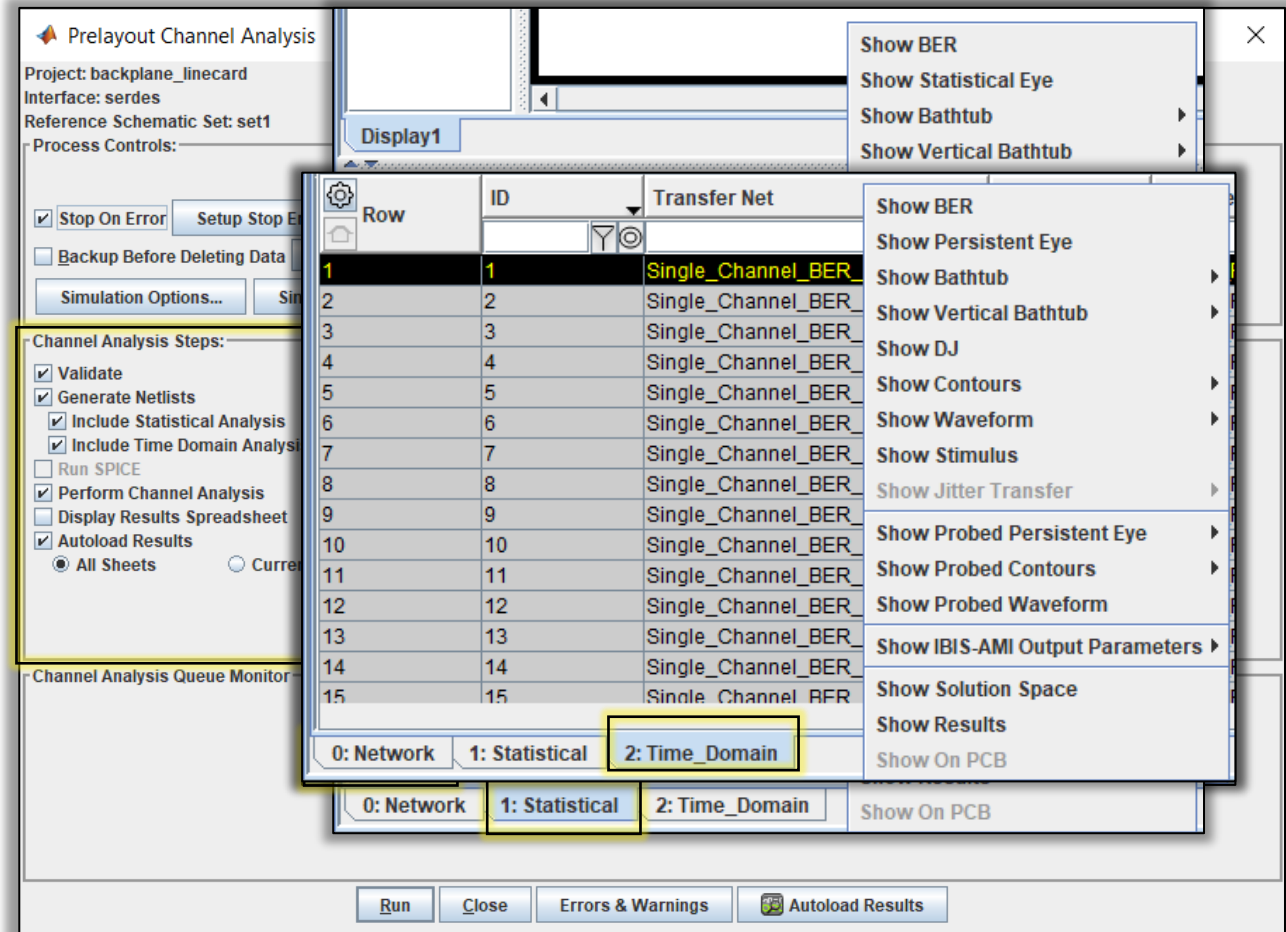
100GBASE-KR4 Compliance Kit
Characterize and validate the performance of a 100GBASE-KR4 channel design.

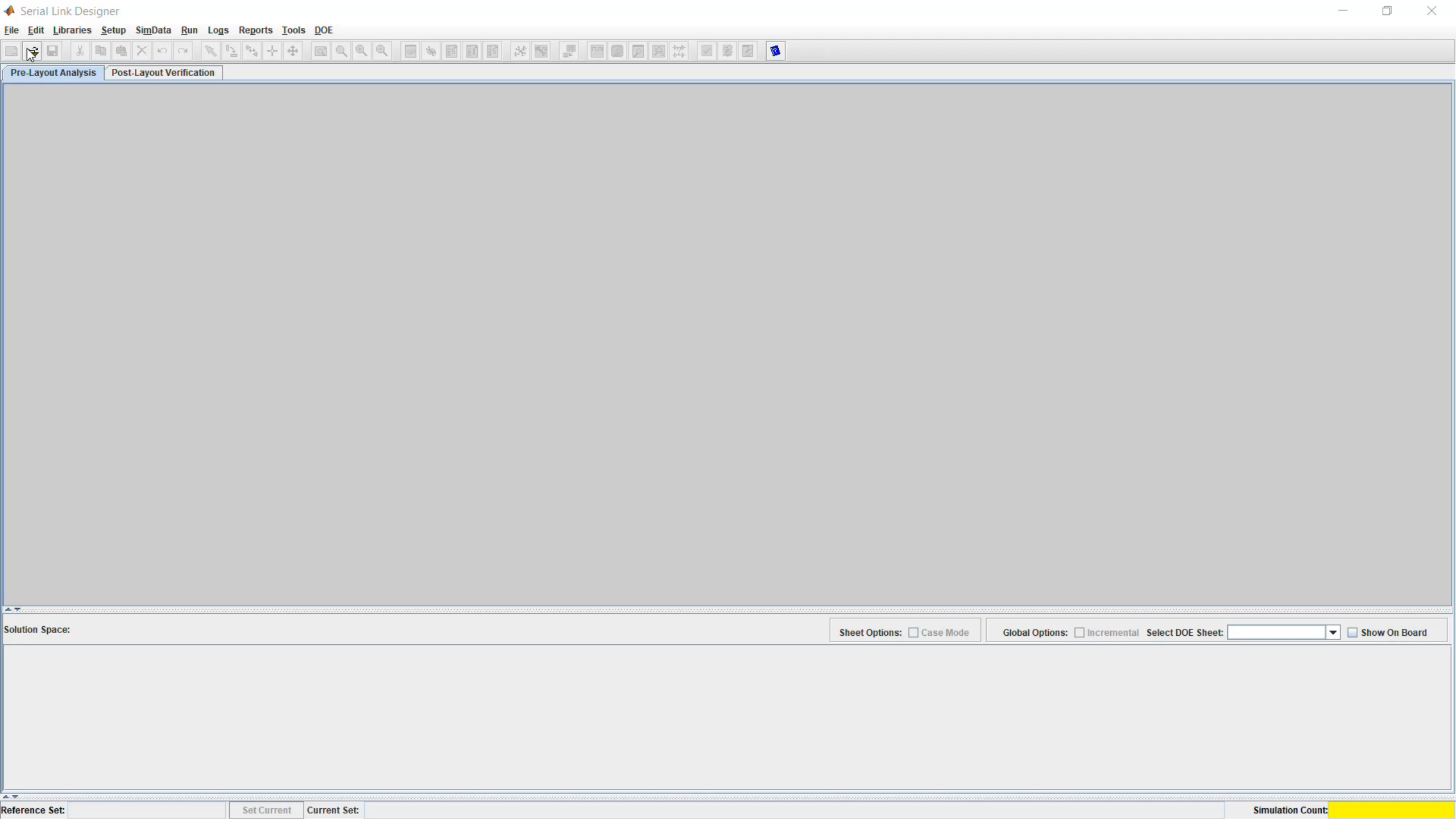
CAUI-4 Chip-to-Chip Compliance Kit
Test the compliance of simulation models and topologies to the CAUI-4 C2C specification.

Over 40 pre-built design kits for industry standards

Simulation Technology

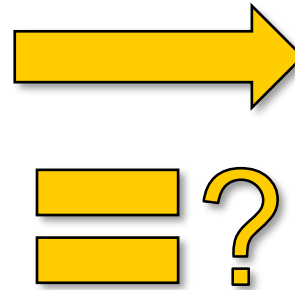
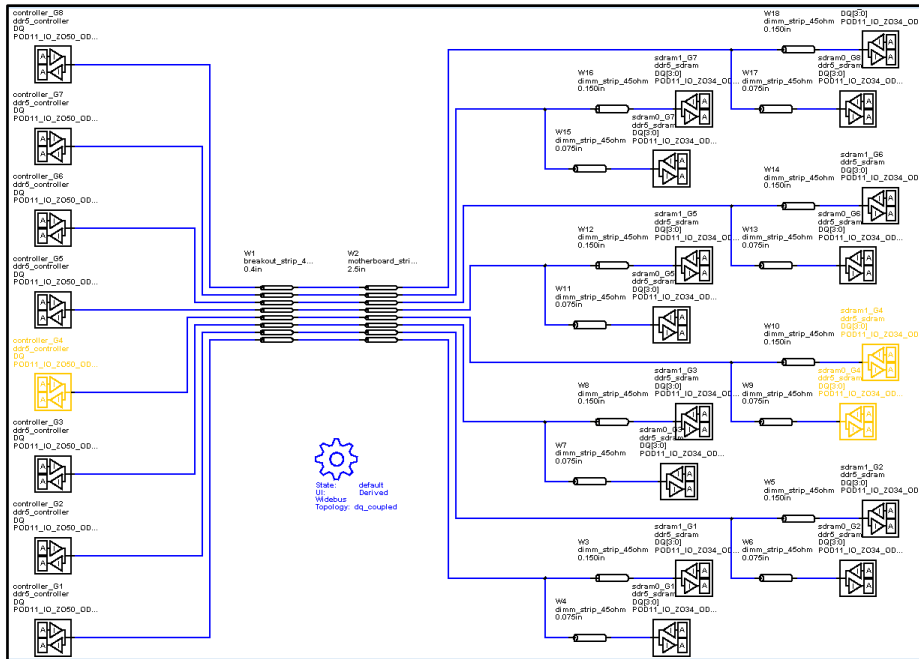
- Perform Channel Analysis – provides network characterization results which includes un-equalized system responses such as impulse response, step response, pulse response, S-Parameters, transfer functions, and more.
- Include Statistical Analysis – results such as statistical eye, BER, bathtub, contour, crosstalk, and more.
- Include Time-Domain Analysis – results such as persistent eye, BER, bathtub, contour, deterministic jitter probability function, crosstalk, and more.



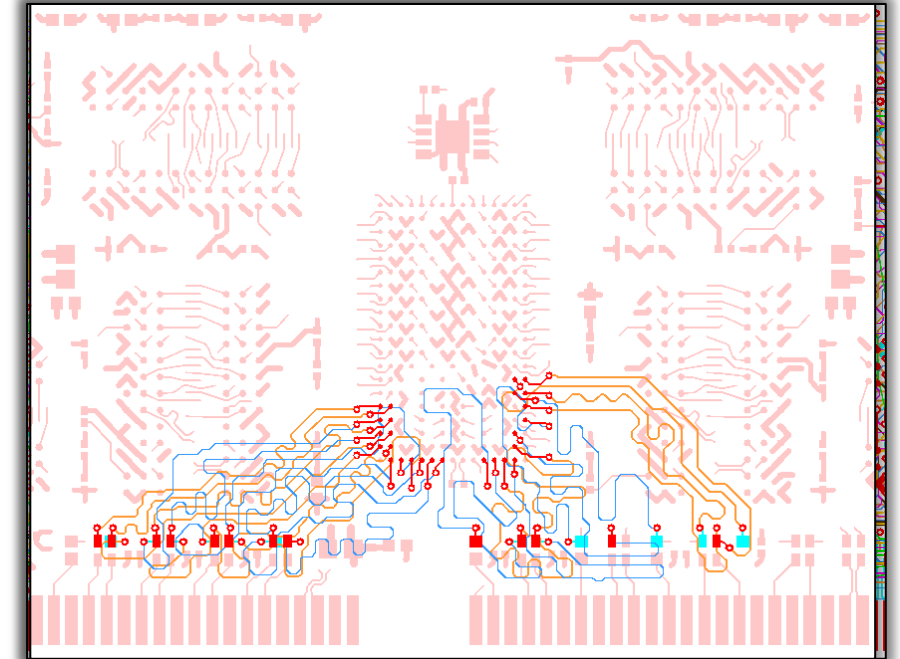


Post-layout

Pre-layout



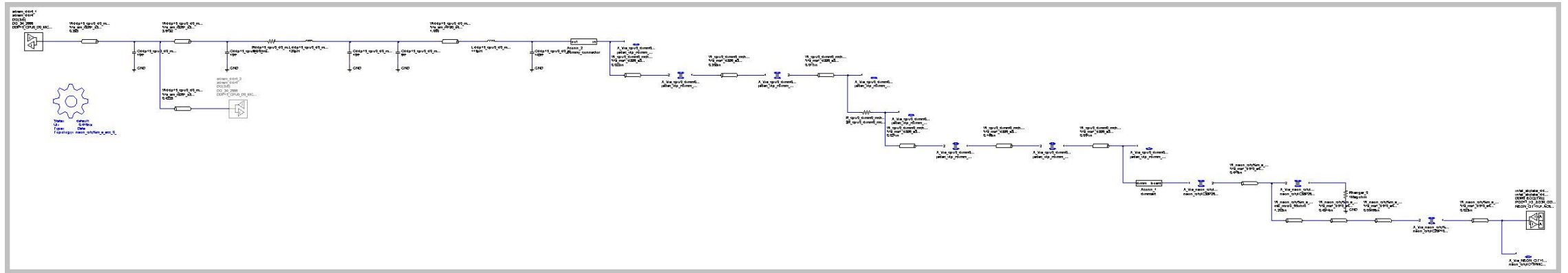
Post-layout



- Use RF PCB Toolbox to import PCB files
- Compare pre- and post-layout nets to each other
- Easily identify any issues
- Incorporate fixes and re-simulate

- Altium Designer
- Cadence Allegro
- Cadence APD
- IBIS EBD
- Intercept Pantheon
- Mentor Board Station
- Mentor Expedition PCB
- Mentor PADS Layout
- ODB++
- Zuken

Post-layout to Pre-layout

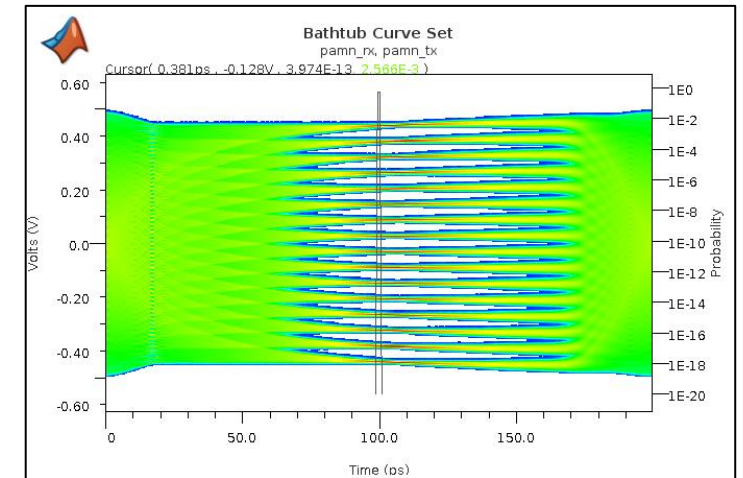
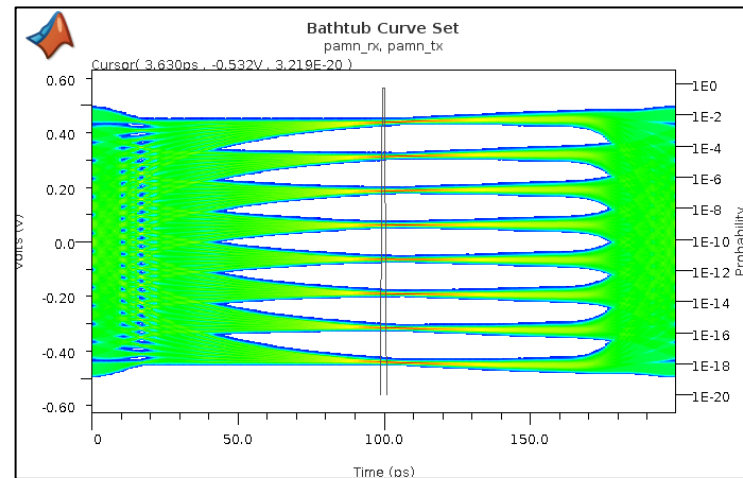
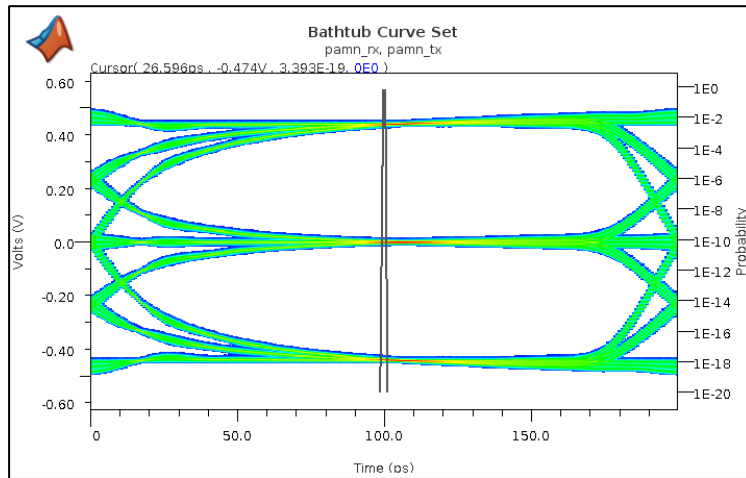


- Includes etch, vias, connectors, and discrete components for each board
- Topology can now be modified using Pre-Layout GUI to find solution

Tap	AMI List	10ohm	12ohm	15ohm	18ohm
ch_ARN83.1.4:R	Soft Range	<none>	<none>	<none>	<none>
_ecc<0>_1.Length	Soft Range	0.750in	1.203in	1.50in	<none>
_ecc<0>_1.W_Model	List	mb_micro_40ohm	mb_micro_50ohm	mb_micro_65ohm	<none>

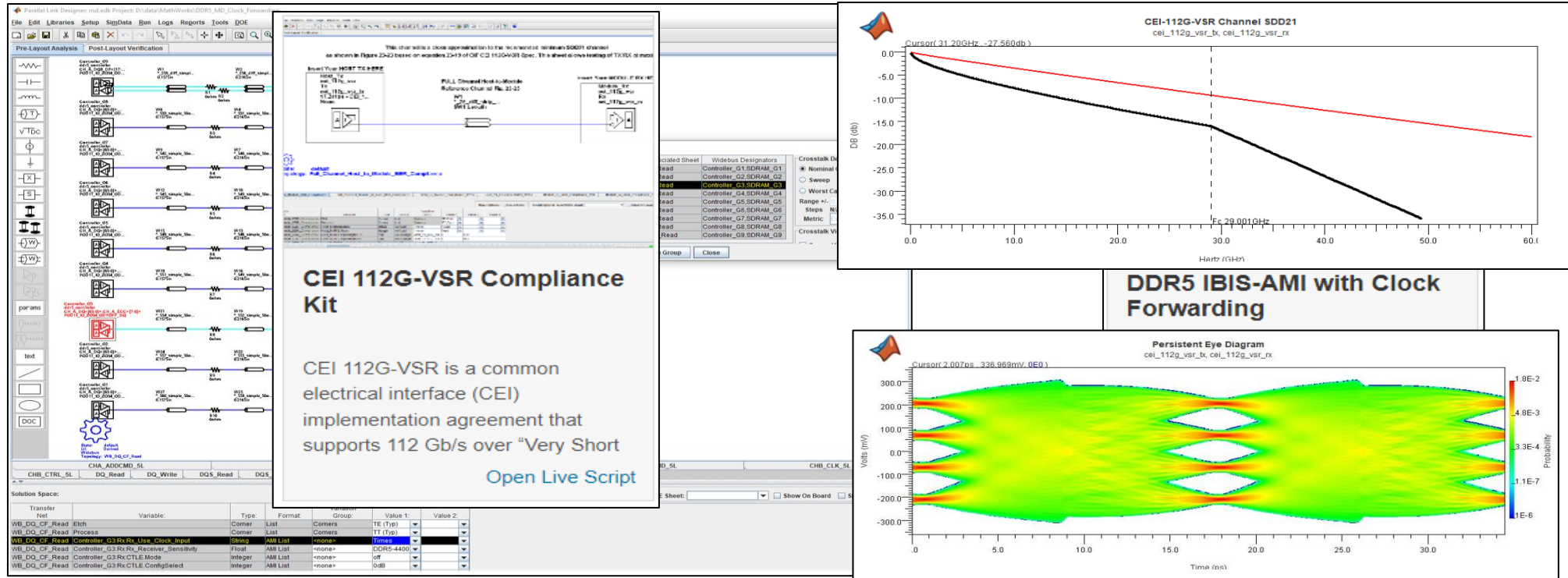
Unset Current Set: set1 STAT Simulation Count: 72 Base SPICE Simulation Count: 72

New for R2022b – PAMn IBIS-AMI Model Support

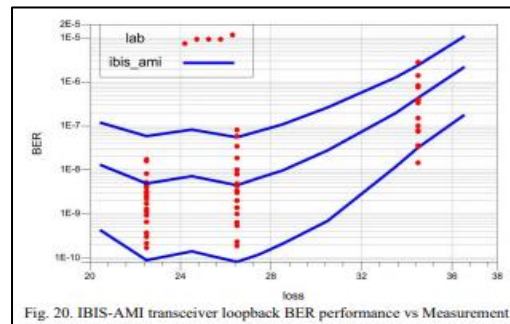
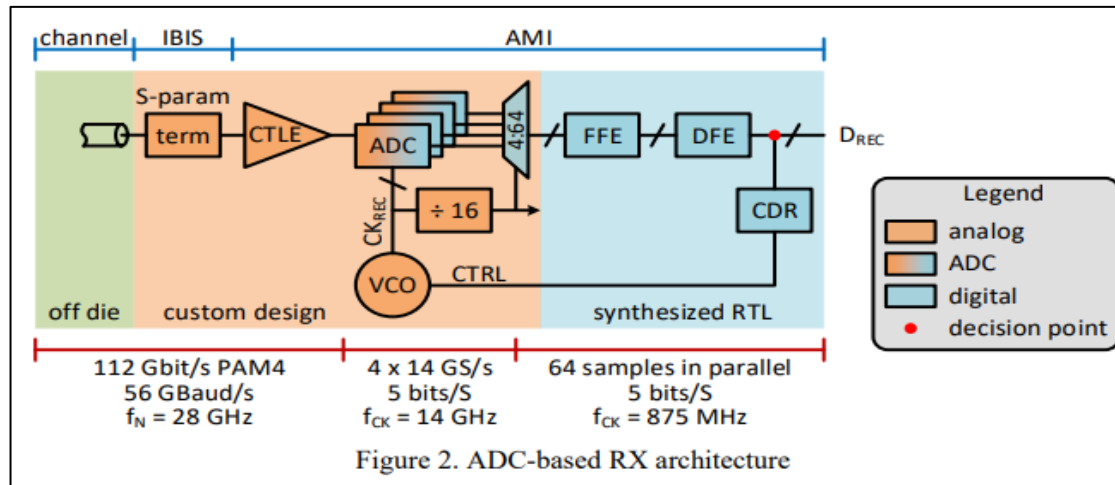


Now use IBIS-AMI models with PAM3, PAM8, PAM16 modulation for use with next generation USB4, GDDR7, MIPI A-PHY, and Automotive SerDes Alliance Motion Link

New for R2022b – Design Kits for Industry Standards



Two DesignCon 2022 Best Paper Award Winners!



DESIGNCON[®] 2022
WHERE THE CHIP MEETS THE BOARD

IBIS-AMI Modeling and Correlation Methodology for ADC-Based SerDes Beyond 100 Gb/s

Aleksey Tyshchenko, SerialLink Systems

aleksey@seriallinksystems.com

David Halupka, SerialLink Systems

Richard Allred, MathWorks

Tripp Worrell, MathWorks

Barry Katz, MathWorks

Clinton Walker, Alphawave IP

Adrien Auge, Alphawave IP

Infineon Accelerates Development of IBIS-AMI Models for SerDes Designs

Challenge

Produce a complete IBIS-AMI model of a SerDes system for a key customer on an aggressive schedule

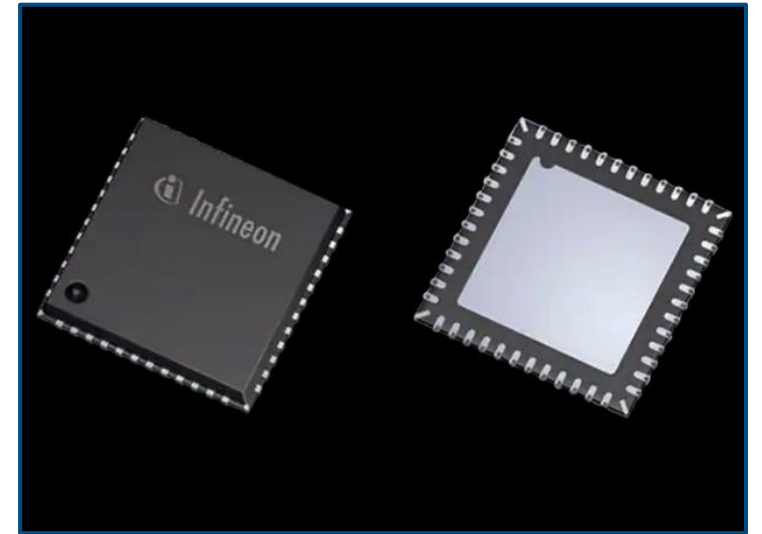
Solution

Use Simulink and SerDes Toolbox to develop, verify, and deliver an IBIS-AMI model in two weeks

Results

- **Complete IBIS-AMI models delivered in two weeks**
- Development ramp-up accelerated
- In-house IBIS-AMI capability developed

[Link to user story](#)

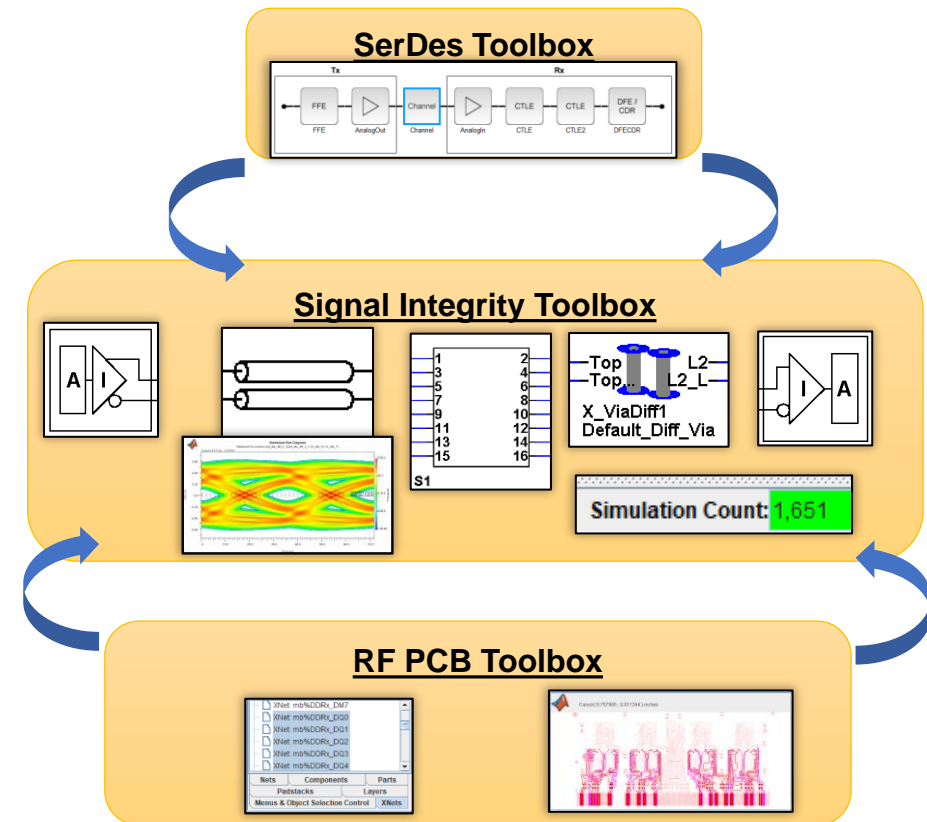
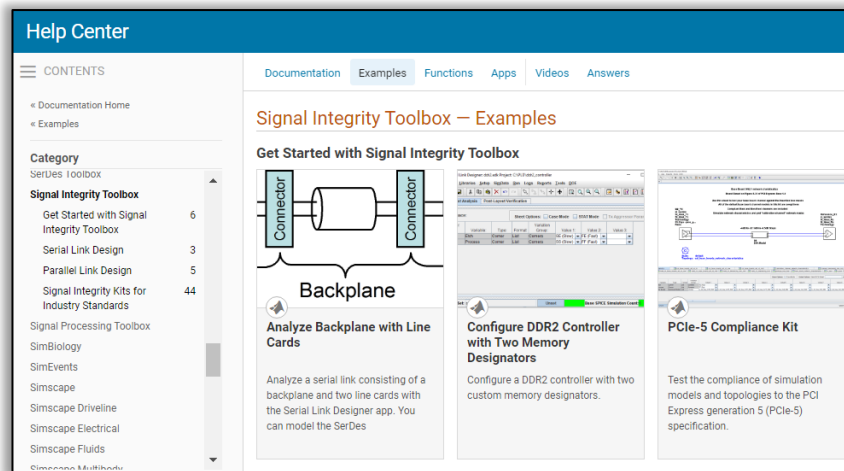
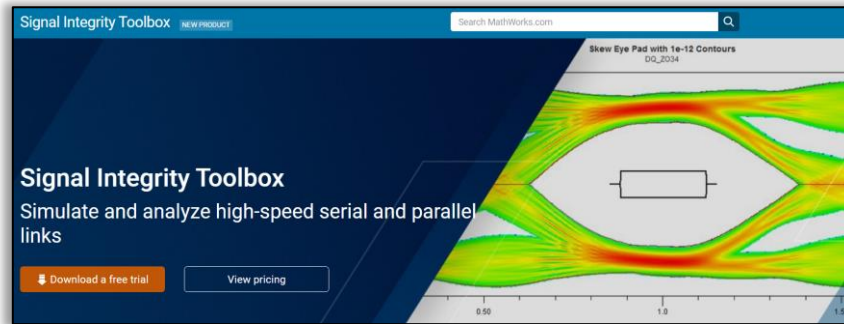


Infineon semiconductor.

"The process of creating and configuring IBIS-AMI models with SerDes Toolbox is straightforward and fast to learn. After completing it once ourselves, we had full control over IBIS-AMI model creation, and eliminated our dependence on contractors."

- Syed Babar Raza, Infineon

Summary



Key takeaway

- Start with statistical analysis
- Refine model with architectural/circuit-level details
- Generate IBIS-AMI model ensuring equivalence
- Regression testing with different channels
- Make sure there is enough margins in all conditions
- Compliance check with the standard



Questions?

